



超级陶粲装置
Super Tau-Charm Facility



STCF Detector Design and R&D

Jianbei Liu

On behalf of the STCF detector group

University of Science and Technology of China

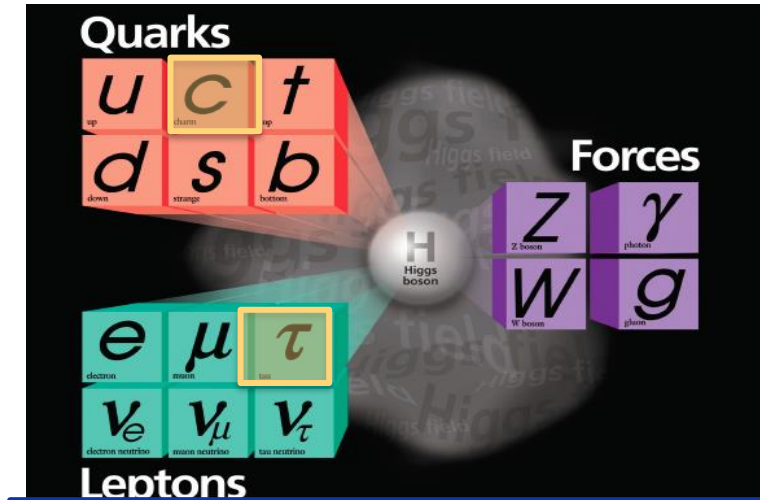
State Key Laboratory of Particle Detection and Electronics

42nd International Conference on High Energy Physics

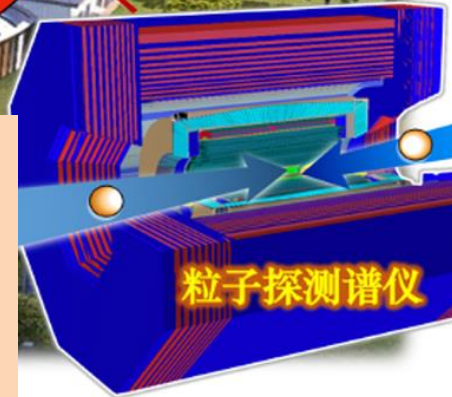
Prague, Czech

July 18, 2024

Super Tau Charm Facility (STCF)



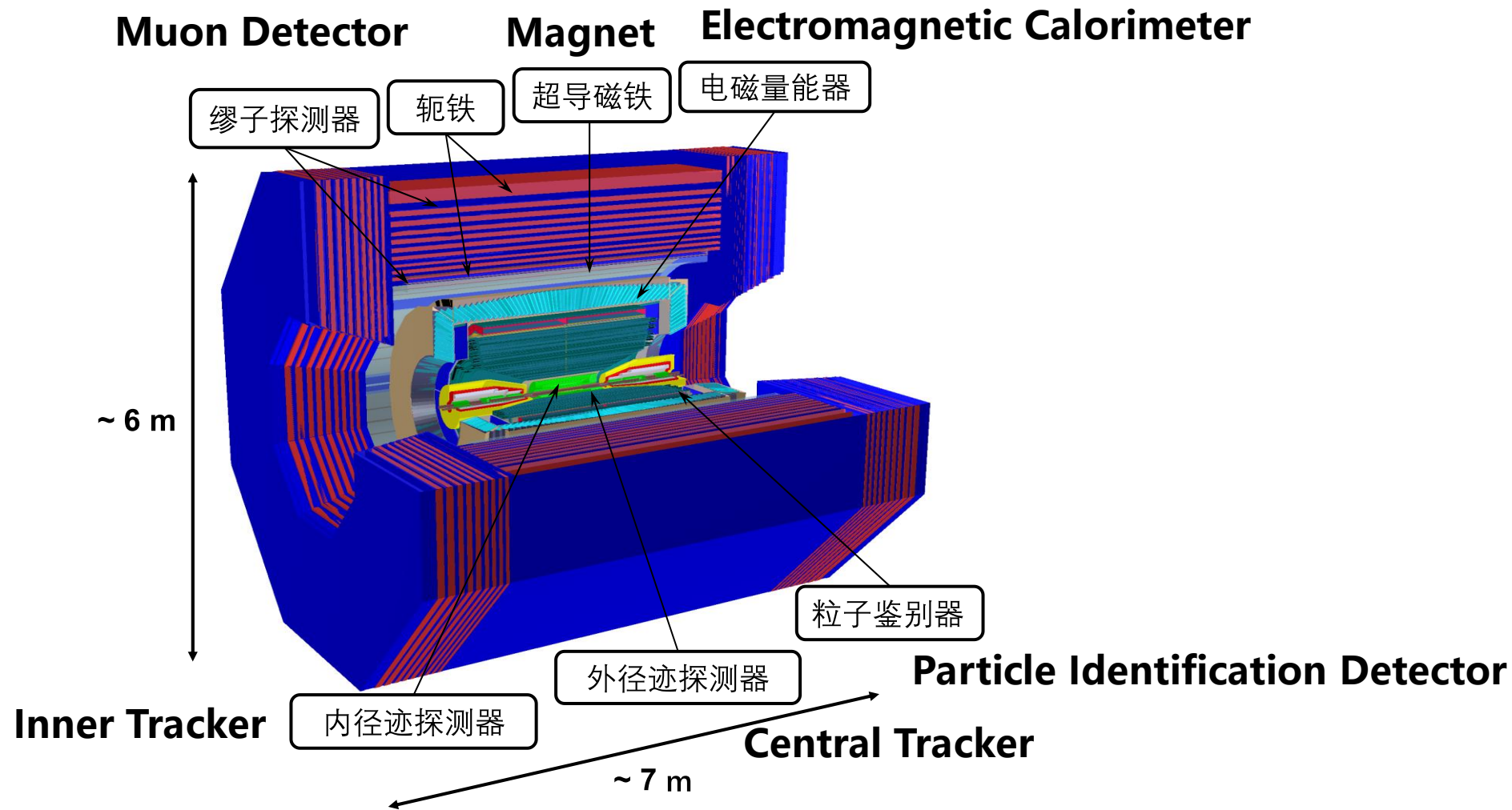
STCF can produce an enormous amount of “clean” tau leptons and charm hadrons, allowing a full exploration of the unique and great physics potential in the tau-charm energy region: QCD, exotic hadrons, flavor physics and CPV, new physics...



- $E_{cm} = 2-7 \text{ GeV}$, $\mathcal{L} > 0.5 \times 10^{35} \text{ cm}^{-2} \text{ s}^{-1}$
- Potential for luminosity upgrade and a polarized electron beam
- Site: Suburban "Future Big Science City" in Hefei
- 14th five-year plan (2021-2025): Design studies and R&D on key technologies, ~0.4 B CNY
- 15th five-year plan (2026-2030): Construction to start during this period, ~6 years, ~4.5 B CNY
- Operating for 15 years to be followed by major upgrades

For more information about the STCF project, please see <https://indico.cern.ch/event/1291157/contributions/5890162/>

STCF Detector Layout

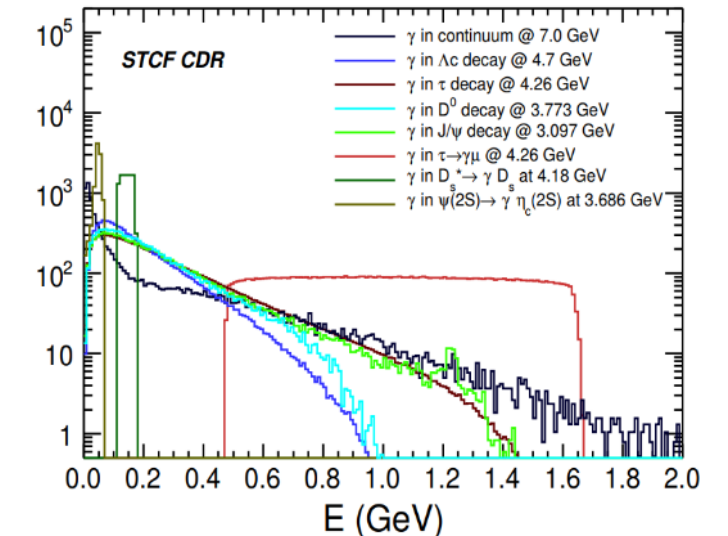
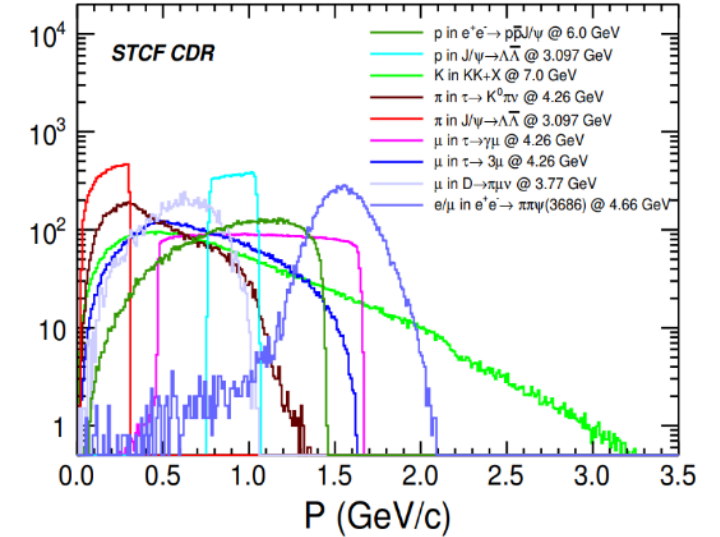


Physics Requirements

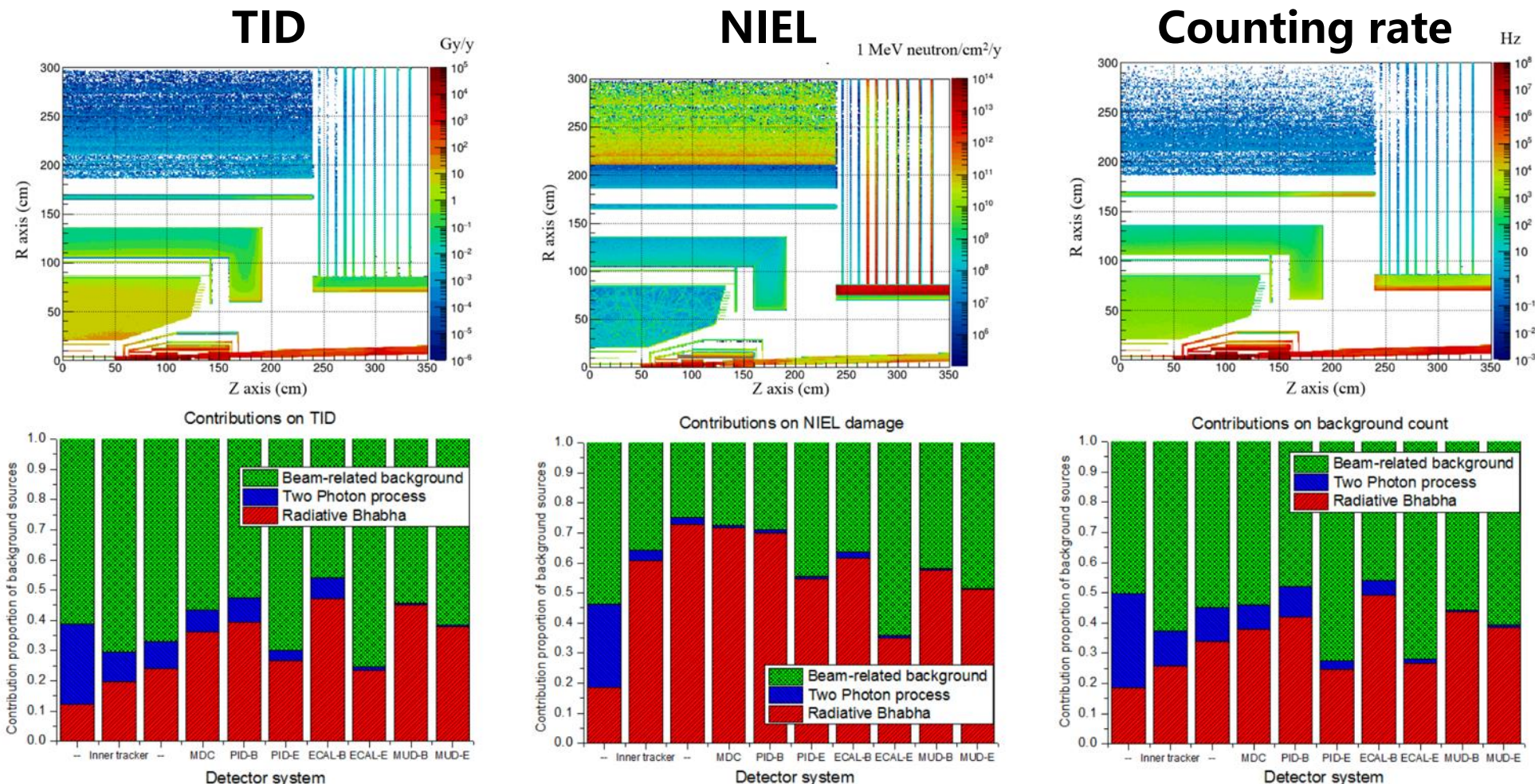
❖ Highly efficient and precise reconstruction of exclusive final states produced in 2-7 GeV e+e- collisions

- ▶ Precise measurement of low-p particles (<1GeV/c) → **low mass**
- ▶ **Excellent PID**: π/K and μ/π separation up to 2 GeV

Process	Physics Interest	Optimized Subdetector	Requirements
$\tau \rightarrow K_s \pi \nu_\tau$, $J/\psi \rightarrow \Lambda \bar{\Lambda}$, $D_{(s)}$ tag	CPV in the τ sector, CPV in the hyperon sector, Charm physics	ITK+MDC	acceptance: 93% of 4π ; trk. effi.: > 99% at $p_T > 0.3$ GeV/c; > 90% at $p_T = 0.1$ GeV/c $\sigma_p/p = 0.5\%$, $\sigma_{\gamma\phi} = 130 \mu\text{m}$ at 1 GeV/c
$e^+e^- \rightarrow KK + X$, $D_{(s)}$ decays	Fragmentation function, CKM matrix, LQCD etc.	PID	π/K and K/π misidentification rate < 2% PID efficiency of hadrons > 97% at $p < 2$ GeV/c
$\tau \rightarrow \mu\mu\mu$, $\tau \rightarrow \gamma\mu$, $D_s \rightarrow \mu\nu$	cLFV decay of τ , CKM matrix, LQCD etc.	PID+MUD	μ/π suppression power over 30 at $p < 2$ GeV/c, μ efficiency over 95% at $p = 1$ GeV/c
$\tau \rightarrow \gamma\mu$, $\psi(3686) \rightarrow \gamma\eta(2S)$	cLFV decay of τ , Charmonium transition	EMC	$\sigma_E/E \approx 2.5\%$ at $E = 1$ GeV $\sigma_{\text{pos}} \approx 5$ mm at $E = 1$ GeV
$e^+e^- \rightarrow n\bar{n}$, $D_0 \rightarrow K_L \pi^+ \pi^-$	Nucleon structure Unity of CKM triangle	EMC+MUD	$\sigma_T = \frac{300}{\sqrt{p^3(\text{GeV}^3)}} \text{ ps}$



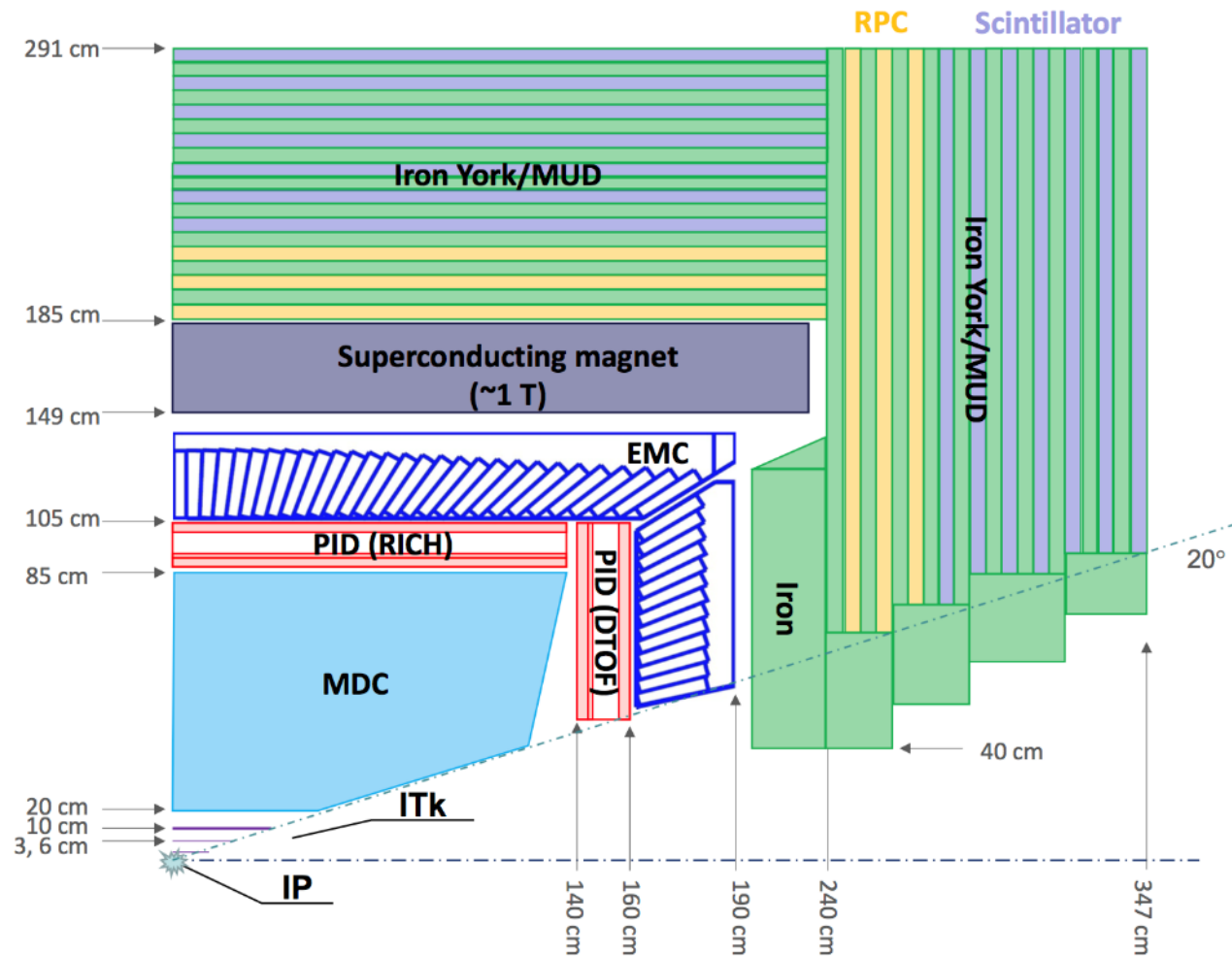
Beam-induced Backgrounds



Inner most detector layer: ~ 3.5 kGy/y, $\sim 2 \times 10^{11}$ 1MeV n-eq/cm²/y, ~ 1 MHz/cm²

The major challenge is to maintain or even enhance the state of the art performance of τ -c detectors in much harsher experimental conditions.

STCF Detector Conceptual Design



Solid Angle Coverage : $94\% \bullet 4\pi$ ($\theta \sim 20^\circ$)

- ❖ **Inner tracker (ITK, two options)**
 - ▶ MPGD: cylindrical MPGD
 - ▶ Silicon: CMOS MAPS
- ❖ **Central tracker (MDC)**
 - ▶ Main drift chamber
- ❖ **PID**
 - ▶ Barrel: **RICH** with CsI-MPGD
 - ▶ Endcaps: DIRC-like TOF (**DTOF**)
- ❖ **EMC**
 - ▶ pure CsI + APD
- ❖ **Muon detector (MUD)**
 - ▶ RPC + scintillator strips
- ❖ **Magnet**
 - ▶ Super-conducting solenoid, 1 T

STCF Physics & Detector CDR

Frontiers of Physics

ISSN 2095-0462
Volume 19 · Number 1
February 2024
物理学前沿

FRONTIERS OF PHYSICS



REPORT

Volume 19 / Issue 1 / 14701 / 2024

STCF conceptual design report (Volume 1): Physics & detector

M. Achasov⁵, X. C. Ai⁵², R. Aliberti³⁸, Q. An^{63,72}, X. Z. Bai^{63,72}, Y. Bai⁶², O. Bakina³⁰, A. Barnyakov^{3,50}, V. Blinov^{3,50,51}, V. Bobrovnikov^{3,51}, D. Bodrov^{23,60}, A. Bogomyagkov³, A. Bondar³, I. Boyko³⁹, Z. H. Bu⁷³, F. M. Cai²⁰, H. Cai⁷⁷, J. J. Cao²⁰, Q. H. Cao⁵⁴, X. Cao³³, Z. Cao^{63,72}, Q. Chang²⁰, K. T. Chao³⁴, D. Y. Chen⁶², H. Chen⁸¹, H. X. Chen⁶², J. F. Chen⁵⁸, K. Chen⁶, L. L. Chen²⁰, P. Chen⁷⁸, S. L. Chen⁶, S. M. Chen⁶⁶, S. Chen⁶⁹, S. P. Chen⁶⁹, W. Chen⁶⁴, X. Chen⁷⁴, X. F. Chen⁵⁸, X. R. Chen³³, Y. Chen³², Y. Q. Chen³⁶, H. Y. Cheng³⁴, J. Cheng⁴⁸, S. Cheng²⁸, T. G. Cheng², J. P. Dai⁸⁰, L. Y. Dai²⁸, X. C. Dai⁵⁴, D. Dedovich³⁰, A. Denig^{19,38}, I. Denisenko³⁰, J. M. Dias⁴, D. Z. Ding³⁸, L. Y. Dong³², W. H. Dong^{63,72}, V. Druzhinin³, D. S. Du^{63,72}, Y. J. Du⁷⁷, Z. G. Du⁴¹, L. M. Duan³³, D. Epifanov³, Y. L. Fan⁷⁷, S. S. Fang³², Z. J. Fang^{63,72}, G. Fedotovitch³, C. Q. Feng^{63,72}, X. Feng⁵⁴, Y. T. Feng^{63,72}, J. L. Fu⁶⁹, J. Gao⁵⁹, P. S. Ge⁷³, C. Q. Geng¹⁵, L. S. Geng², A. Gilman⁷¹, L. Gong¹³, T. Gong²¹, B. Gou³³, W. Gradl³⁸, J. L. Gu^{63,72}, A. Guevara⁴, L. C. Gui²⁶, A. Q. Guo³⁸, F. K. Guo^{4,69,2}, J. C. Guo^{63,72}, J. Guo⁵⁹, Y. P. Guo¹¹, Z. H. Guo¹⁶, A. Guskov³⁰, K. L. Han⁶⁹, L. Han^{63,72}, M. Han^{63,72}, X. Q. Hao²⁰, J. B. He⁶⁹, S. Q. He^{63,72}, X. G. He⁵⁹, Y. L. He²⁰, Z. B. He³³, Z. X. Heng²⁰, B. L. Hou^{63,72}, T. J. Hou⁷⁴, Y. R. Hou⁶⁹, C. Y. Hu⁷⁴, H. M. Hu³², K. Hu⁵⁷, R. J. Hu³³, X. H. Hu⁹, Y. C. Hu⁴⁹, J. Hua⁸¹, G. S. Huang^{63,72}, J. S. Huang¹⁷, M. Huang⁶⁹, Q. Y. Huang⁶⁹, W. Q. Huang⁶⁹, X. T. Huang⁵⁷, X. J. Huang³³, Y. B. Huang¹⁴, Y. S. Huang⁶⁴, N. Hüsken³⁸, V. Ivanov³, O. P. Ji²⁰, J. J. Jia⁷⁷, S. Jia⁶², Z. K. Jia^{63,72}, H. B. Jiang⁷⁷, J. Jiang⁵⁷, S. Z. Jiang¹⁴, J. B. Jiao⁵⁷, Z. Jiao²⁴, H. J. Jing⁶⁹, X. L. Kang⁸, X. S. Kang¹⁵, B. C. Ke⁸², M. Kenzie⁵, A. Khoukaz⁷⁶, I. Koop^{3,50,51}, E. Kravchenko^{3,51}, A. Kuzmin³, Y. Lei⁶⁹, E. Levichev³, C. H. Li⁴², C. Li⁵⁵, D. Y. Li³³, F. L. Li^{63,72}, G. Li⁵⁵, G. Li¹⁵, H. B. Li^{32,69}, H. Li^{63,72}, H. N. Li⁶¹, H. J. Li²⁰, H. L. Li²⁷, J. M. Li^{63,72}, J. Li³², L. Li⁵⁶, L. Li⁵⁹, L. Y. Li^{63,72}, N. Li⁶⁴, P. R. Li⁴¹, R. H. Li³⁰, S. Li⁵⁹, T. Li⁵⁷, W. J. Li²⁰, X. Li³³, X. H. Li⁷⁴, X. Q. Li⁶, X. H. Li^{63,72}, Y. Li⁷⁹, Y. Y. Li⁷², Z. J. Li³³, H. Liang^{63,72}, J. H. Liang⁸¹, Y. T. Liang³³, G. R. Liao¹³, L. Z. Liao³⁵, Y. Liao⁶¹, C. X. Lin⁶⁹, D. X. Lin³³, X. S. Lin^{63,72}, B. J. Liu³², C. W. Liu¹⁵, D. Liu^{63,72}, F. Liu⁶, G. M. Liu⁶¹, H. B. Liu¹⁴, J. Liu⁵⁴, J. J. Liu⁷⁴, J. B. Liu^{63,72}, K. Liu⁴¹, K. Y. Liu⁴⁵, K. Liu⁵⁹, L. Liu^{63,72}, Q. Liu⁶⁹, S. B. Liu^{63,72}, T. Liu¹¹, X. Liu⁴¹, Y. W. Liu^{63,72}, Y. Liu⁸², Y. L. Liu^{63,72}, Z. Q. Liu⁵⁷, Z. Y. Liu⁴¹, Z. W. Liu⁴⁵, I. Logashenko³, Y. Long^{63,72}, C. G. Lu³³, J. X. Lu², N. Lu^{63,72}, Q. F. Lü³⁶, Y. Lu⁷, Y. Lu⁶⁹, Z. Lu⁶², P. Lukin³, F. J. Luo⁷⁴, T. Luo¹¹, X. F. Luo⁶, H. J. Lyu²⁴, X. R. Lyu⁶⁹, J. P. Ma³⁵, P. Ma³⁵, Y. Ma¹⁵, Y. M. Ma³⁵, F. Maas^{19,38}, S. Malde⁷¹, D. Matvienko³, Z. X. Meng⁷⁰, R. Mitchell²⁰, A. Nefediev⁴⁰, Y. Nefedov³⁰, S. L. Olsen^{22,53}, Q. Ouyang^{32,63}, P. Pakhlov²³, G. Pakhlova^{23,52}, X. Pan⁶⁹, Y. Pan⁶², E. Passemar^{29,65,67}, Y. P. Pei^{63,72}, H. P. Peng^{63,72}, L. Peng²⁷, X. Y. Peng⁸, X. J. Peng⁴¹, K. Peters¹², S. Pivovarov⁵, E. Pyata³, B. B. Qi^{63,72}, Y. Q. Qi^{63,72}, W. B. Qian⁶⁹, Y. Qian³³, C. F. Qiao⁶⁹, J. J. Qin⁷⁴, J. J. Qin^{63,72}, L. Q. Qin¹³, X. S. Qin⁵⁷, T. L. Qiu³³, J. Rademacker⁶⁸, C. F. Redmer³⁸, H. Y. Sang^{63,72}, M. Saur⁵⁴, W. Shan²⁶, X. Y. Shan^{63,72}, L. L. Shang²⁰, M. Shao^{63,72}, L. Shekhtman³, C. P. Shen¹¹, J. M. Shen²⁸, Z. T. Shen^{63,72}, H. C. Shi^{63,72}, X. D. Shi^{63,72}, B. Shwartz³, A. Sokolov³, J. J. Song²⁰, W. M. Song³⁶, Y. Song^{63,72}, Y. X. Song¹⁰, A. Sukharev^{3,51}, J. F. Sun²⁰, L. Sun⁷⁷, X. M. Sun⁶, Y. J. Sun^{63,72}, Z. P. Sun³³, J. Tang⁹¹, S. S. Tang^{63,72}, Z. B. Tang^{63,72}, C. H. Tian^{63,72}, J. S. Tian⁷⁸, Y. Tian³³, Y. Tikhonov³, K. Todyshchev^{3,51}, T. Uglov³², V. Vorobyev³, B. D. Wan¹⁵, B. L. Wang⁶⁹, B. Wang^{63,72}, D. Y. Wang⁵⁴, G. Y. Wang²¹, G. L. Wang¹⁷, H. L. Wang⁶¹, J. Wang⁴⁹, J. H. Wang^{63,72}, J. C. Wang^{63,72}, M. L. Wang³², R. Wang^{63,72}, R. Wang³³, S. B. Wang⁵⁹, W. Wang⁵⁹, W. P. Wang^{63,72}, X. C. Wang³⁰, X. D. Wang⁷⁴, X. L. Wang^{63,72}, X. L. Wang³⁰, X. P. Wang², X. F. Wang¹¹,

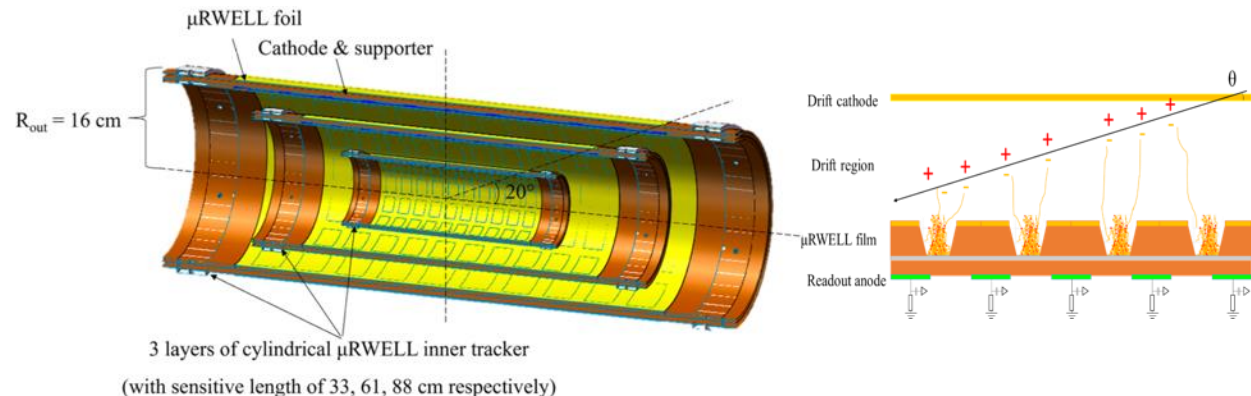
3.2	Experimental Conditions	70
3.2.1	Machine Parameters	70
3.2.2	Machine Detector Interface	70
3.2.3	Beam Background	71
3.2.4	Conclusion	77
3.3	Detector Design Overview	78
3.3.1	General Considerations	78
3.3.2	Overall Detector Concept	79
3.4	Inner Tracker (ITK)	82
3.4.1	Introduction	82
3.4.2	Performance Requirements and Technology Choices	82
3.4.3	μ RWELL-based Inner Tracker	82
3.4.4	MAPS-based Inner Tracker	90
3.4.5	Pileup and Radiation Effects	93
3.4.6	Conclusion and Outlook	94
3.5	Main Drift Chamber (MDC)	95
3.5.1	Introduction	95
3.5.2	Conceptual Design of the MDC	95
3.5.3	MDC Simulation and Optimization	97
3.5.4	Expected Performance	100
3.5.5	Pileup and Radiation Effects	104
3.5.6	Readout Electronics	105
3.5.7	Conclusion	106
3.6	Particle Identification in the Barrel (RICH)	107
3.6.1	Introduction	107
3.6.2	RICH Detector Concept	107
3.6.3	RICH Detector Performance Simulation	112
3.6.4	Detector Layout	116
3.6.5	Readout Electronics	116
3.6.6	Summary and Outlook	118
3.7	Particle Identification in the Endcap (DToF)	119
3.7.1	Introduction	119
3.7.2	DToF Conceptual Design	119
3.7.3	DToF Performance Simulation	121
3.7.4	DToF Structure Optimization	126
3.7.5	Background Simulation	129
3.7.6	Readout Electronics	131
3.7.7	Summary and Outlook	132
3.8	ElectroMagnetic Calorimeter (EMC)	133
3.8.1	Introduction	133
3.8.2	EMC Conceptual Design	133
3.8.3	Expected Performance of the EMC	138
3.8.4	Pileup Mitigation	143
3.8.5	Readout Electronics	146
3.8.6	EMC R&D	146
3.8.7	Summary	149

82 institutions, 453 authors

arXiv:2303.15790

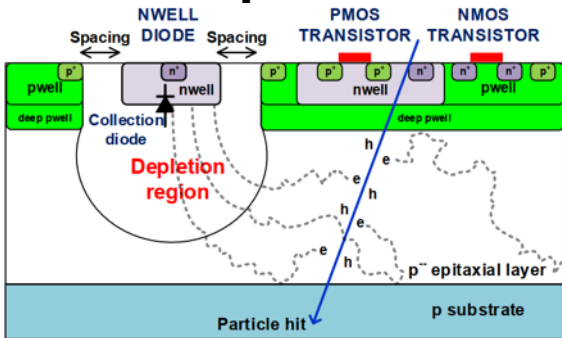
Tracking System : ITK + MDC

ITK Gaseous option : MPGD

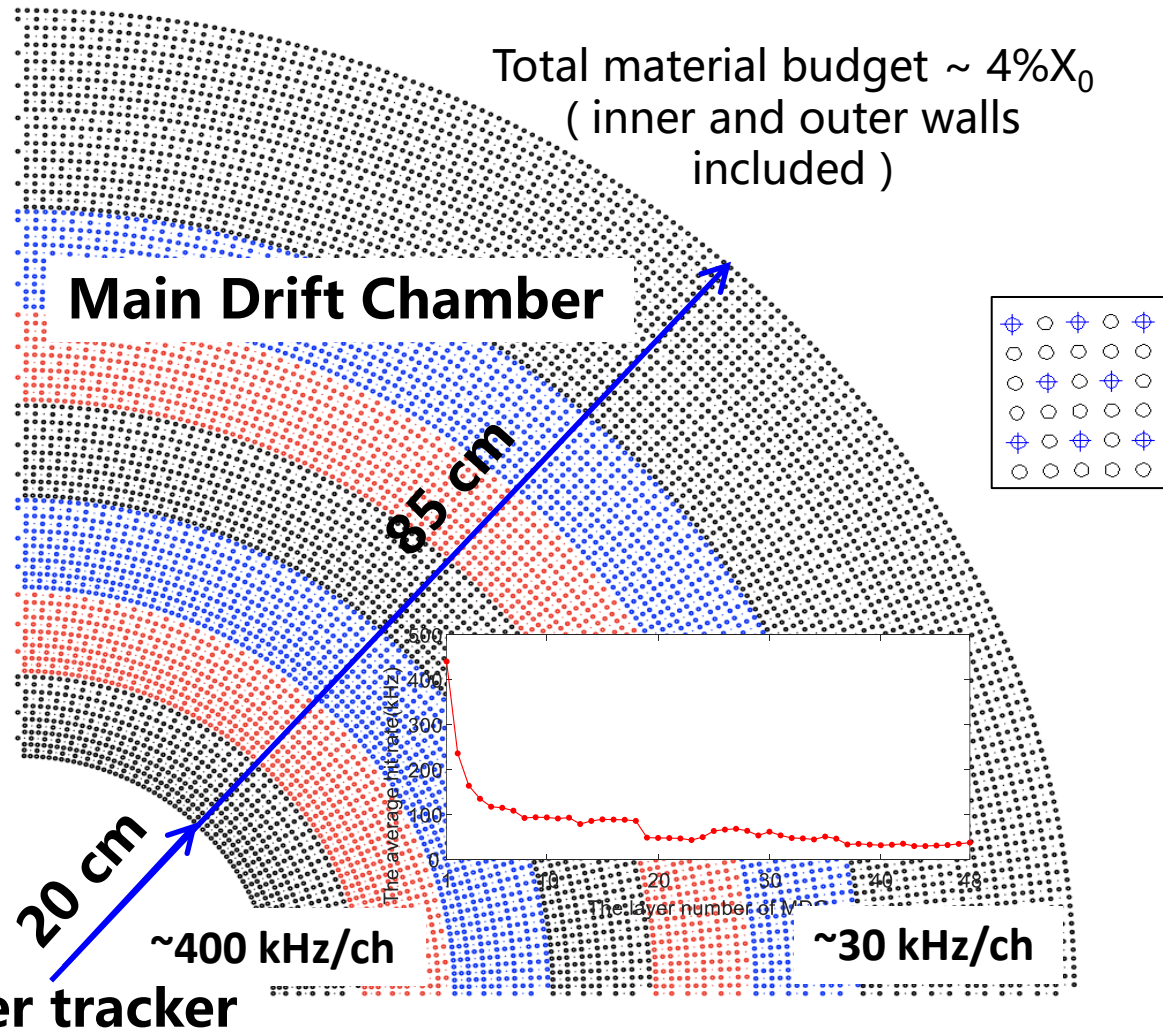


Material budget $\sim 0.3\%X_0/\text{layer}$

ITK Silicon option: CMOS MAPS



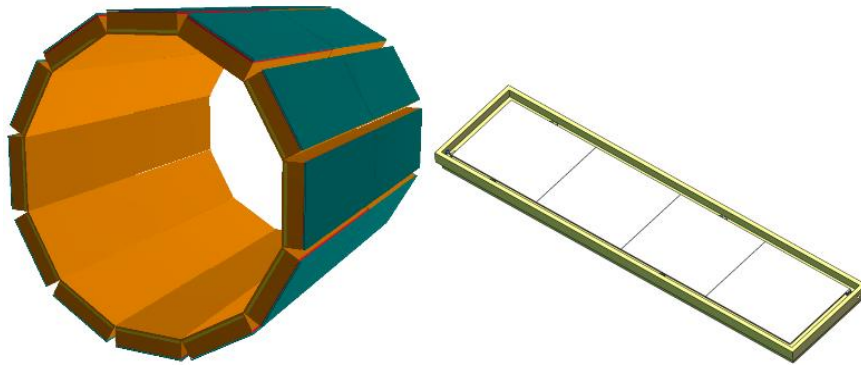
单片有源像素探测器



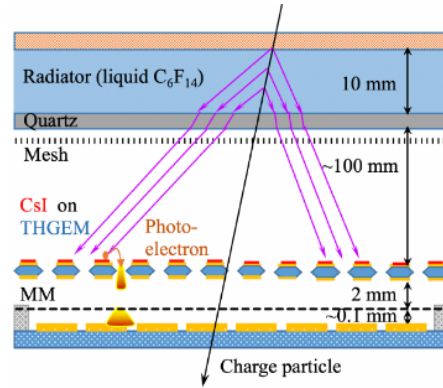
Inner-outer separate designs to accommodate different levels of radiation background

PID, EMC, MUD

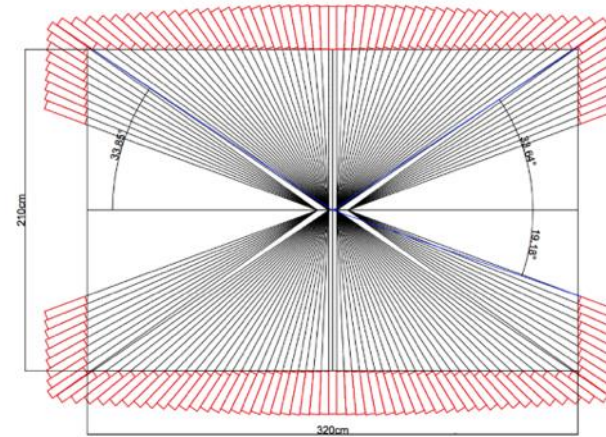
- Barrel PID: A RICH detector using MPGD (THGEM with CsI + MM) for photon detection



Material budget <math> < 0.3X_0 </math>

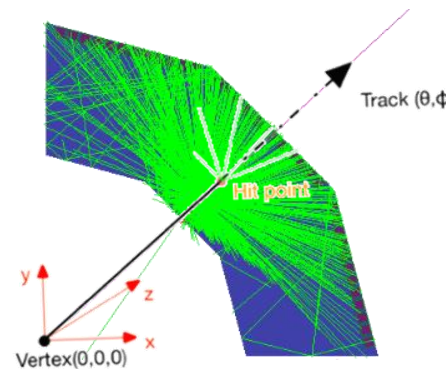
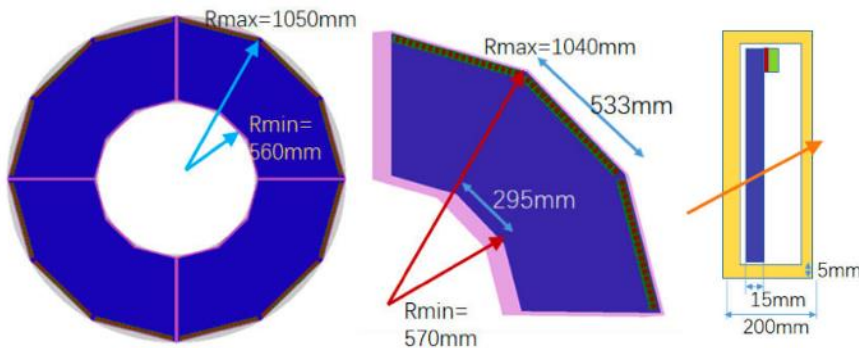


- EMC: A pure-CsI crystal calorimeter to tackle a high level of background (~1MHz/ch)

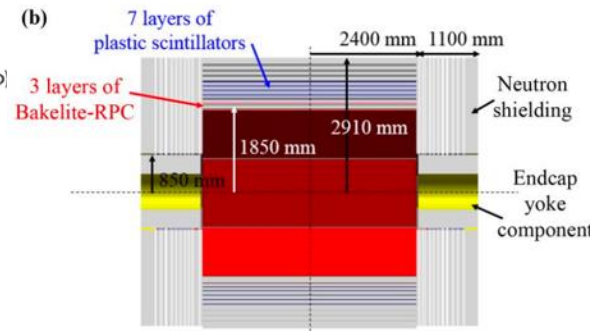


- Crystal size 28cm (15X0) 5x5cm²
- ~ 8670 crystals
- 4 large area APDs (1x1cm²) to enhance light yield

- Endcap PID: A DIRC-like high-resolution TOF detector (DTOF ~ 30ps), quartz plate + MCP-maPMT



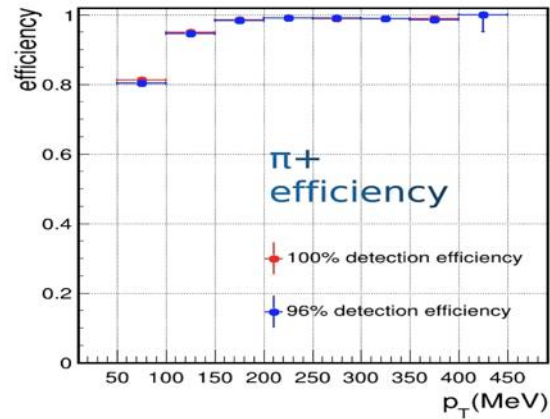
- MUD: A RPC-scintillator hybrid detector to optimize muon and neutral hadron ID



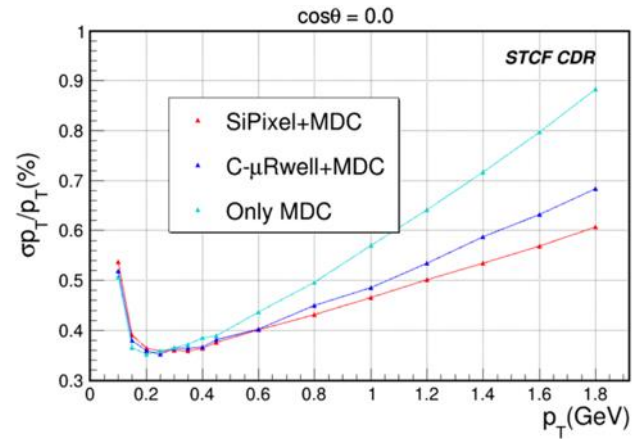
Parameter	Baseline design
R_{in} [cm]	185
R_{out} [cm]	291
R_e [cm]	85
L_{Barrel} [cm]	480
T_{Endcap} [cm]	107
Segmentation in ϕ	8
Number of detector layers	10
Iron yoke thickness [cm]	4/4/4.5/4.5/6/6/6/8/8
($\lambda=16.77$ cm)	Total: 51 cm, 3.04λ
Solid angle	79.2% $\times 4\pi$ in barrel
	14.8% $\times 4\pi$ in endcap
	94% $\times 4\pi$ in total
Total area [m ²]	Barrel ~717
	Endcap ~520
	Total ~1237

Expected Performance

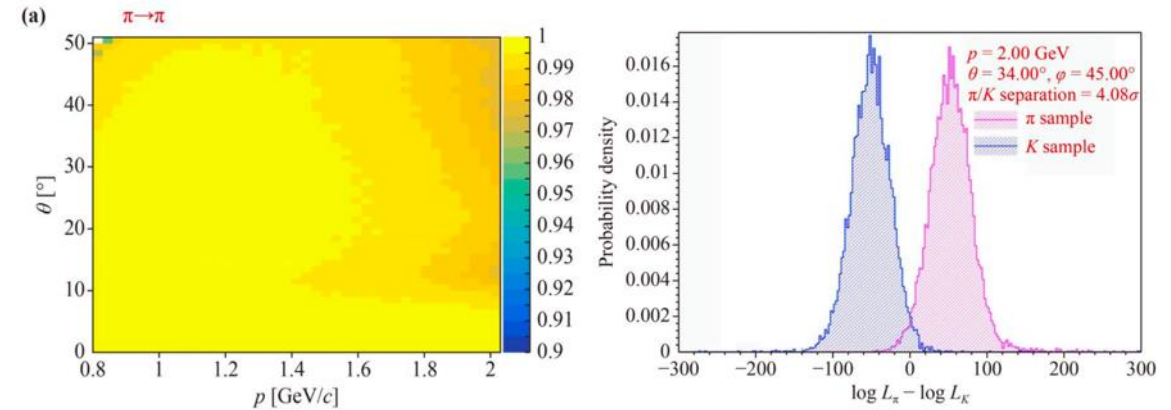
Tracking efficiency



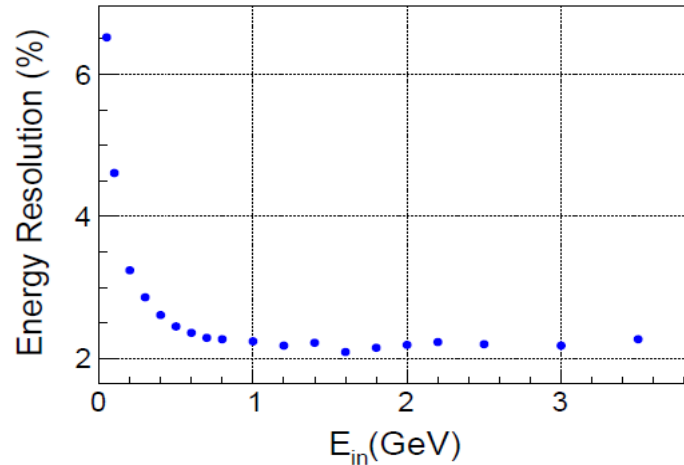
Momentum resolution



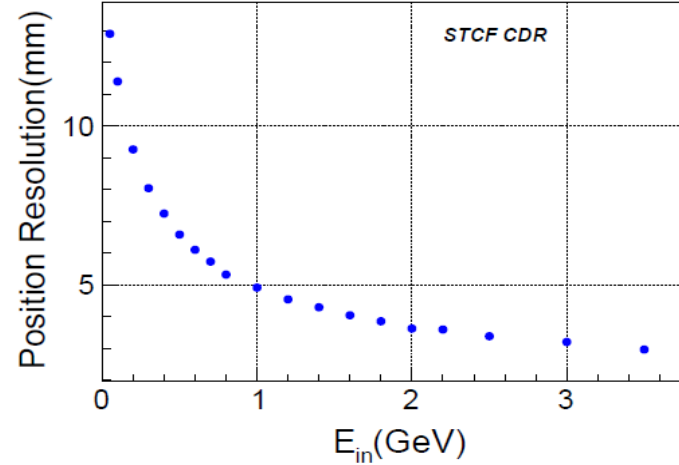
Pion/K separation capability



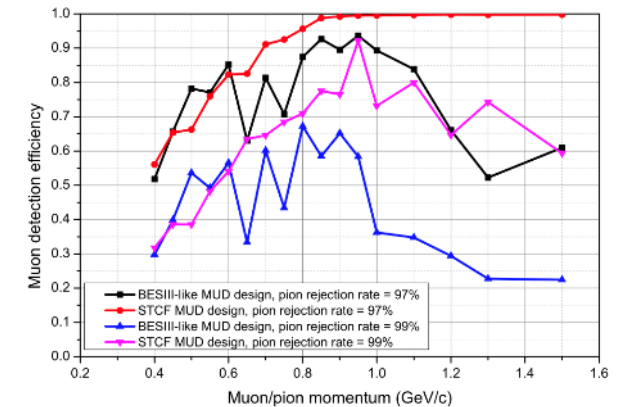
Photon energy resolution



Photon position resolution



Muon identification efficiency



STCF R&D Project Kick-Off and Review Meetings



Kick-off Meeting, Aug. 2023, USTC

More than 30 academicians of CAS, as well as government officials of Anhui province and Hefei city, along with representatives from various domestic research institutions, totaling 170 attendees.

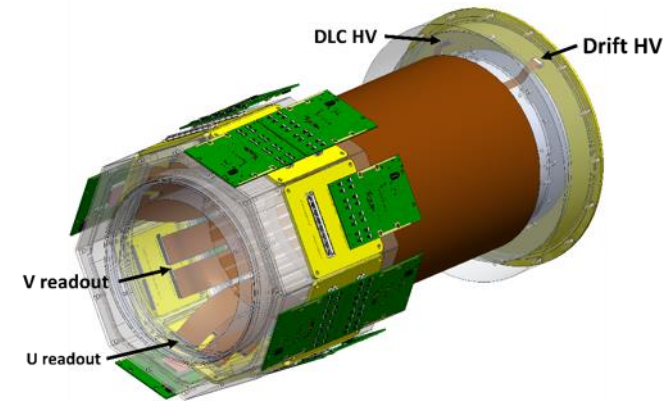
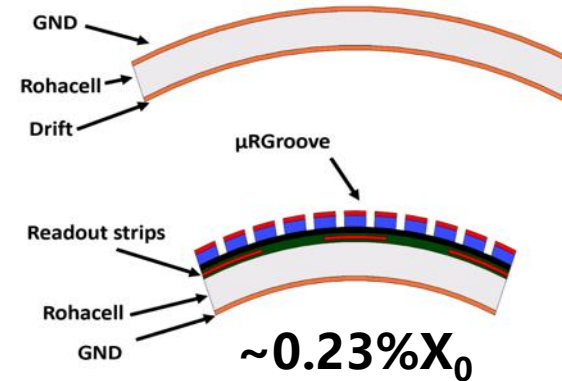
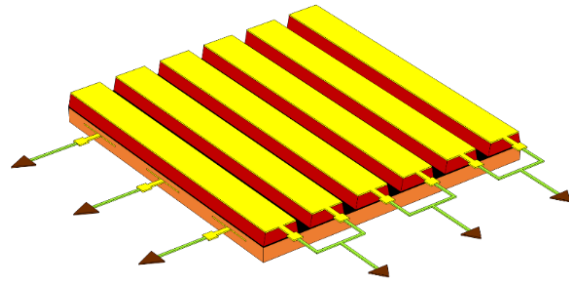
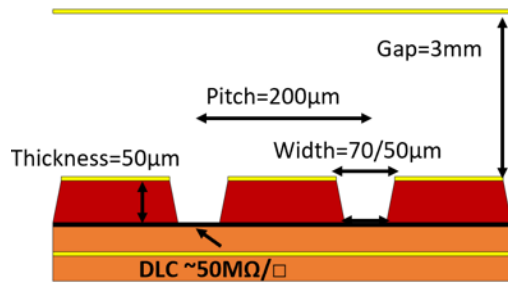


R&D Project Review, Dec. 2023, USTC

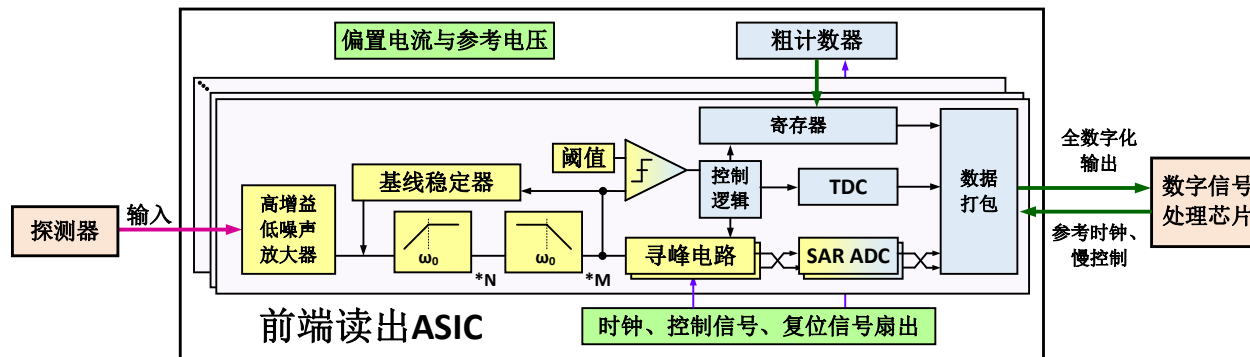
Organized by Development and Reform Commissions of Anhui province and Hefei city. The R&D project was approved for a budget of 364 M CNY and is jointly funded by Anhui, Hefei and USTC.

ITK-MPGD: μ RGroove

- μ RGroove : A single-stage MPGD involving no stretching or tensioning, 2D strip readout without charge sharing (large S/N), high rate with fast grounding, easy to make a cylinder, low mass, low production cost



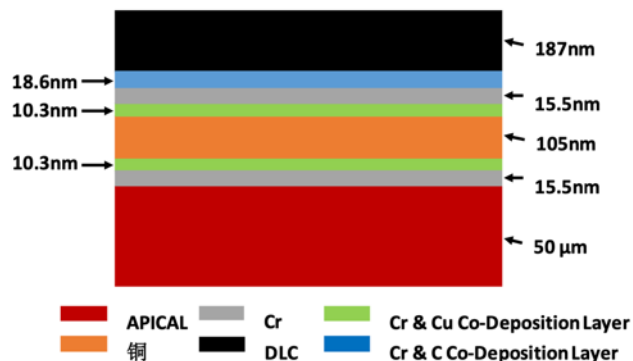
- High-rate readout ASIC for MPGD (averaged hit rate of 400 kHz/ch)



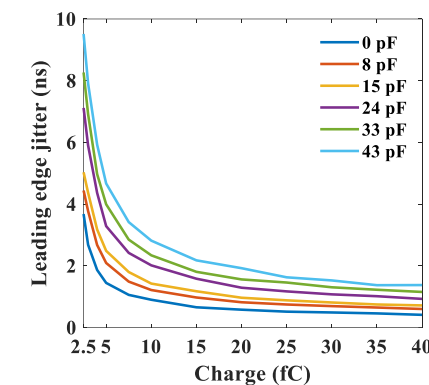
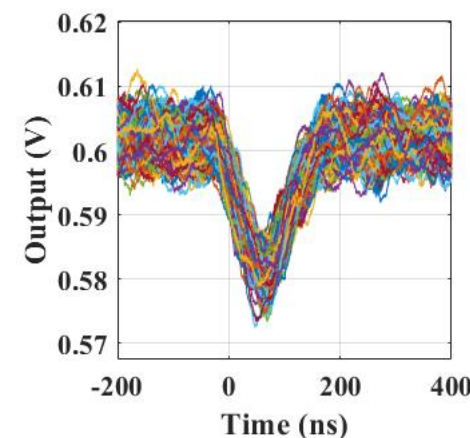
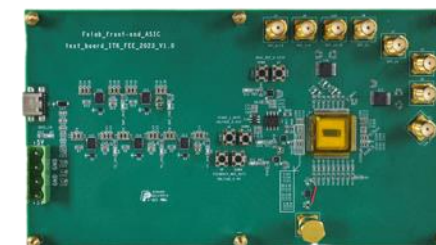
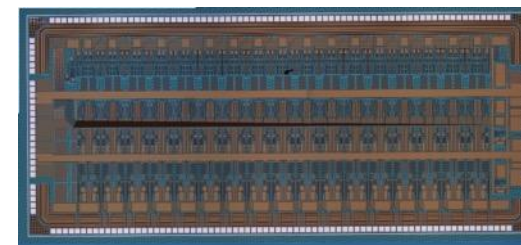
ASIC Specs	Demands
Charge Range	40 fC
Charge precision	~ 1 fC RMS
Time precision	< 10 ns RMS
Max. event rate	4 MHz

ITK-MPGD R&D

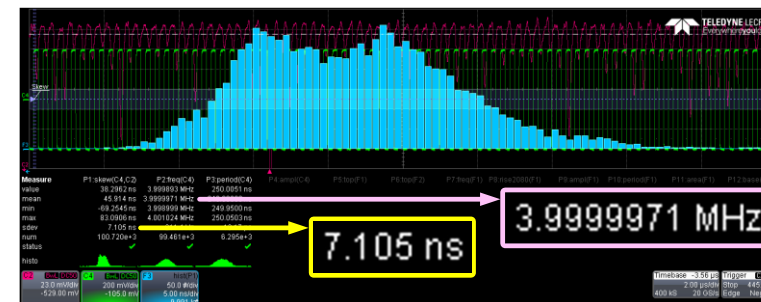
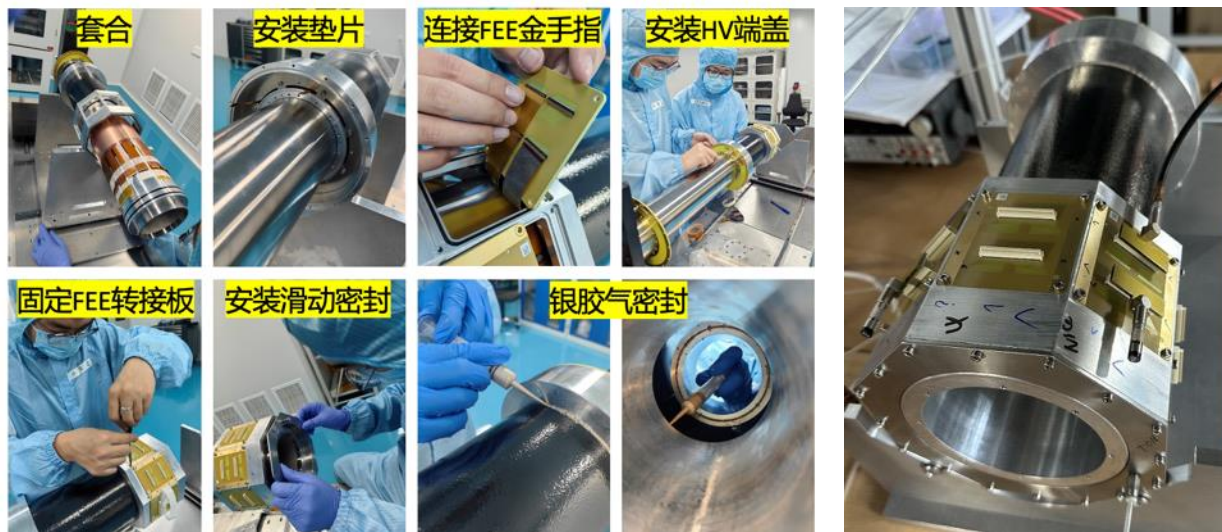
Development of low mass electrodes



ASIC design and development



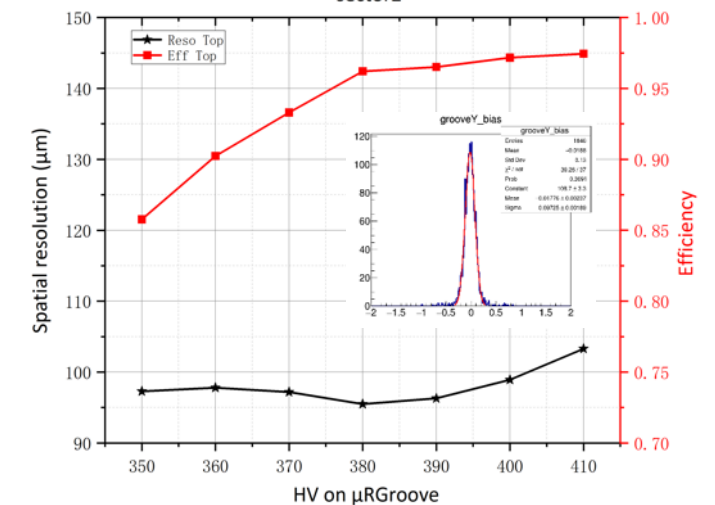
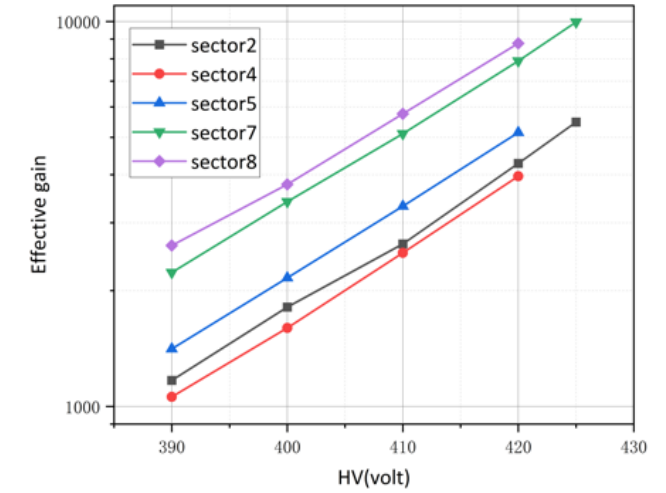
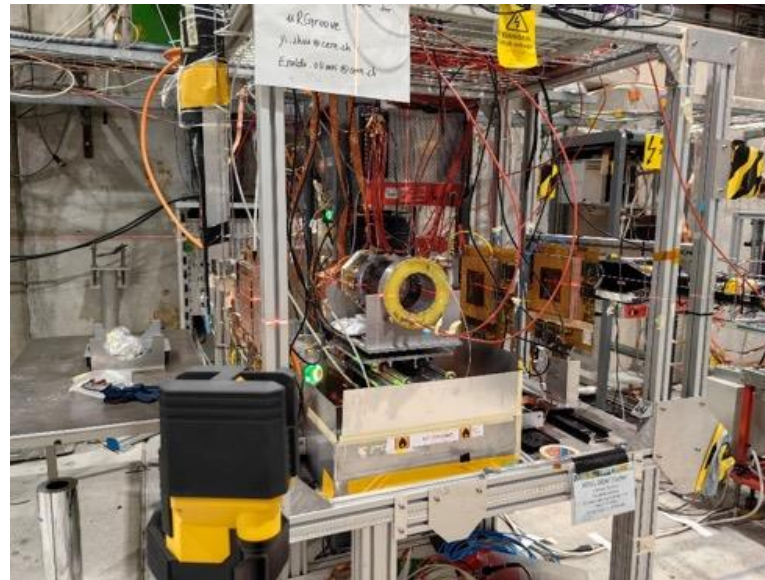
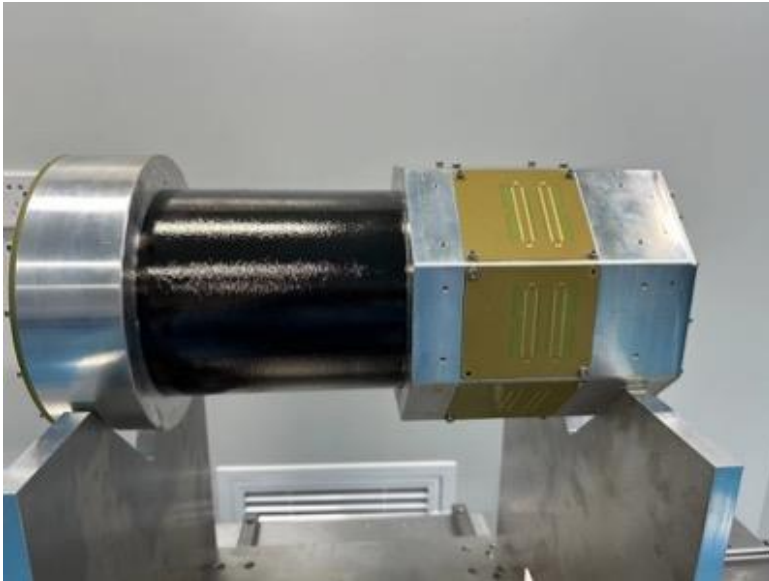
Fabricating cylindrical structure



Tested the ASIC chip by feeding simulated detector output pulses to the chip at 4MHz with 35pF

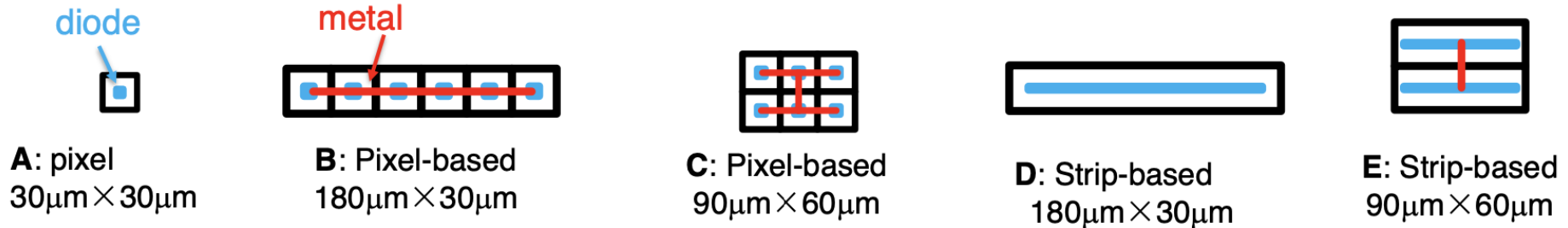
Inner Layer Prototype

- Built a cylindrical μ RGroove prototype for the ITK inner most layer
- Tested the prototype with ^{55}Fe source in lab and SPS muon beam at CERN
- Effective gain ~ 5000 - 10000 for most sectors
- Spatial resolution < 100 μm and efficiency $> 95\%$
- The detector design and fabrication will be optimized in many aspects based on the prototyping experience

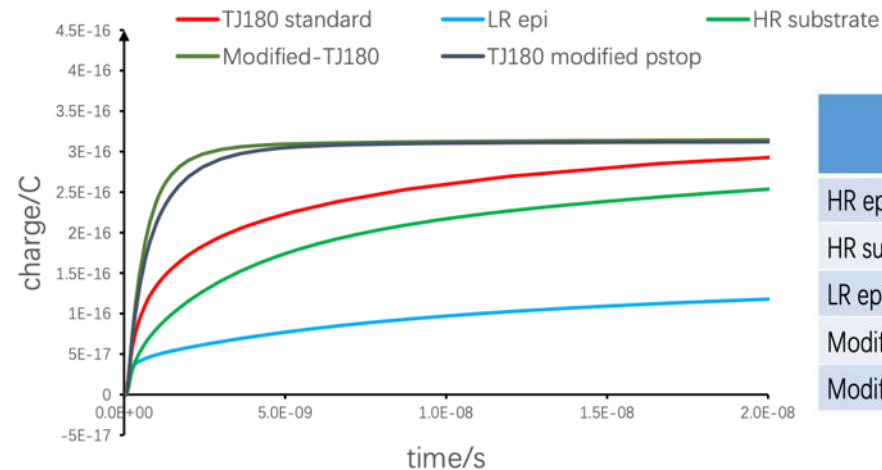


ITK-MAPS

- Aiming for a low-power MAPS chip design (required for a low-mass system) with timing and charge measurement capability: position, time and charge (TOT)
- Low mass outweighs position resolution: exploring large pixel size to reduce power density



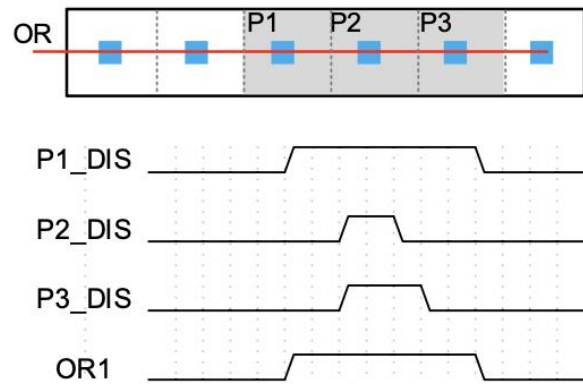
- CMOS techniques being explored:
 - TowerJazz 180nm (HR epi),
 - NexChip FCIS/BCIS 90nm (LR epi)
 - GSMC 130nm (HR substrate)



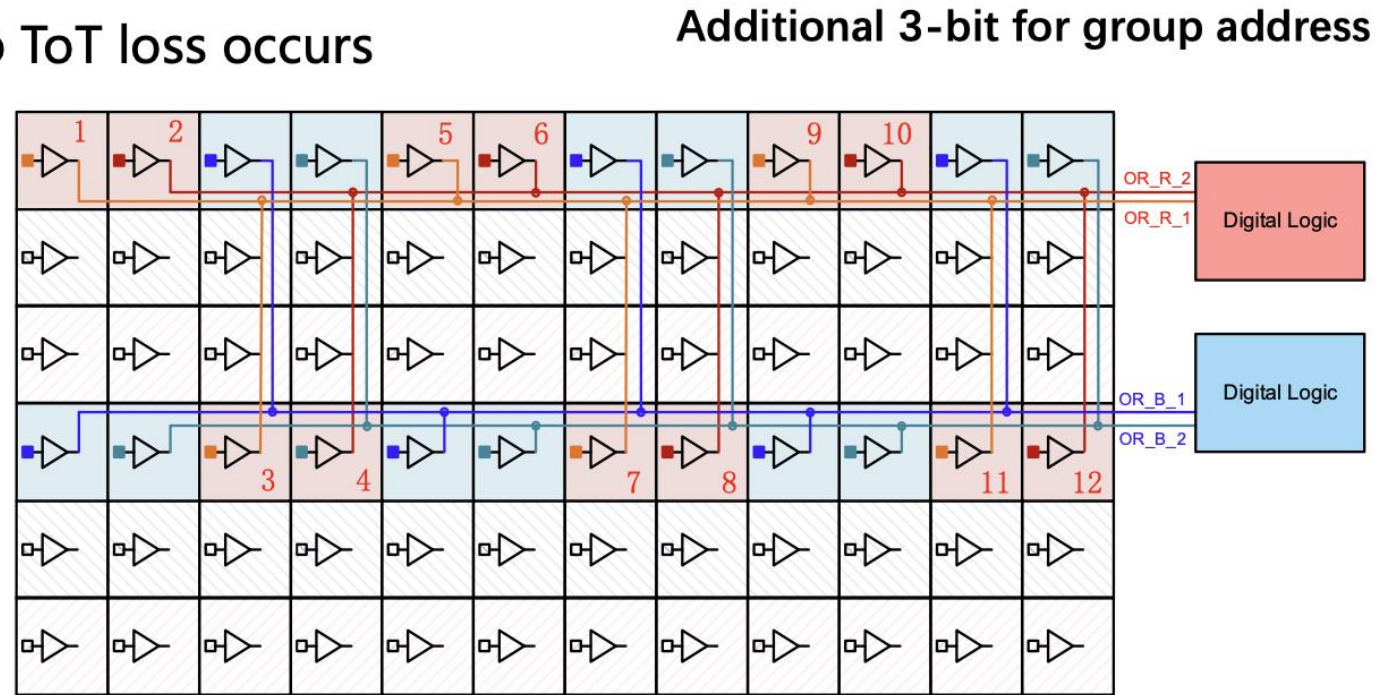
	Collected charge (e)	Collection time(ns)
HR epi (TJ180nm)	2039.81	20.56
HR substrate	2477.65	89.72
LR epi	1089.64	74.57
Modified-TJ180nm	1969.85	1.81
Modified-TJ180nm pstop	1952.04	2.47

Super Pixel Design

- ❖ Combining non-adjacent pixels: avoid ToT loss
- ❖ Super pixel with 6×12 pixel array
 - 6 sets of digital readout logic
 - When cluster size $< 3 \times 4$, no ToT loss occurs



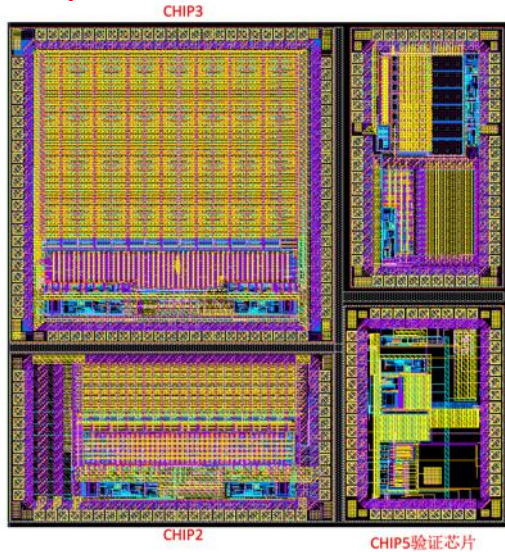
Combining adjacent pixels
→ ToT loss



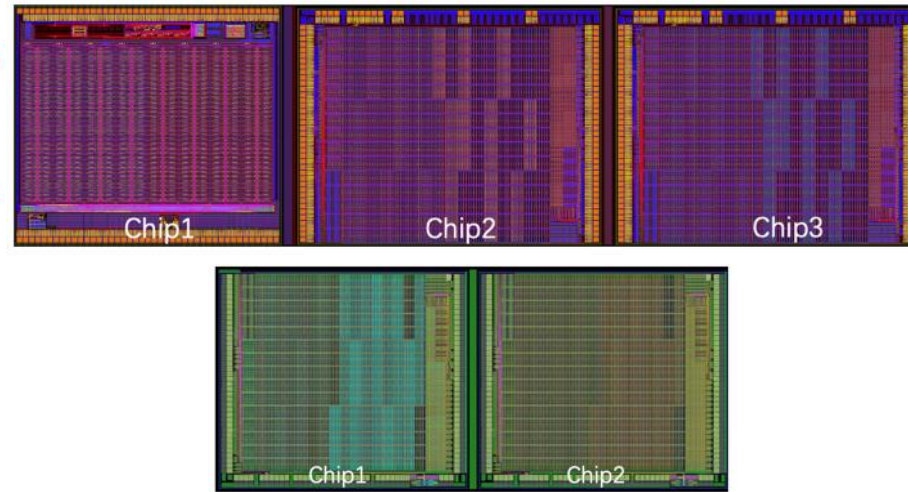
- **Providing both high position and high time resolutions for low power consumption**

ITK MAPS Designs

TowerJazz 180nm
Taped out in March 2024



NexChip FCIS/BCIS 90nm
Taped out in May 2024



Simulated performance

	TJ-MAPS	GSMC-MAPS
Current	800 nA/pix	120*6 nA/pix
Supply Voltage	1.8 V	1.2 V
Threshold	309.0 e ⁻	153.8 e ⁻
ENC	11.4 e ⁻	5.1 e ⁻
Mismatch	5.7 e ⁻	5.8 e ⁻
t_r @400 e⁻	200 ns	81 ns

GSMC 130nm to be taped out in July 2024

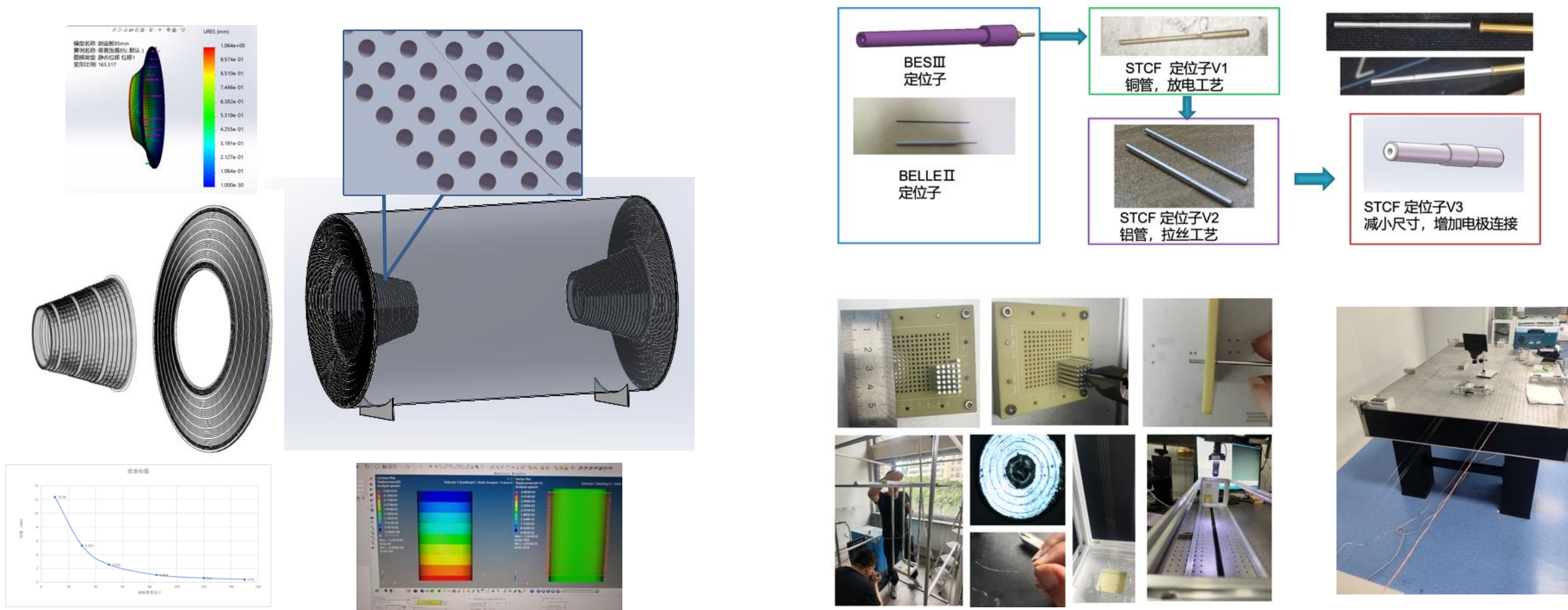


Items	Power consumption	Notes
Analog in pixel matrix	~26 mW/cm ²	Strip-based
	~15 mW/cm ²	Pixel-based
Timestamp clock distribution	12.2 mW/cm ²	
Dynamic power consumption of the pixel matrix	2.4 mW/cm ²	with a data rate of 8.7 MHz/cm ²
Periphery	23.5 mW	32MHz event rate
PLL, serializer, LVDS	39 mW	x 2 data/clock output
Analog configuration	20 mW	
Total	222.6 mW	Strip-based
	184.6 mW	Pixel-based

- Strip-based: 55.7 mW/cm²
- Pixel-based: 46.2 mW/cm²

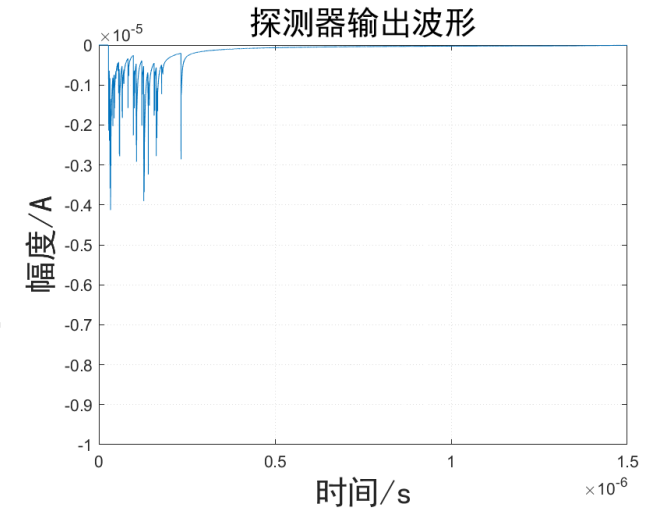
Main Drift Chamber

- Preliminary mechanical design and structural analysis
- Big challenges from super-small cells (5mm*5mm, distance between wires ~2.5mm)
- Ongoing R&D on feedthroughs, wires and chamber stringing

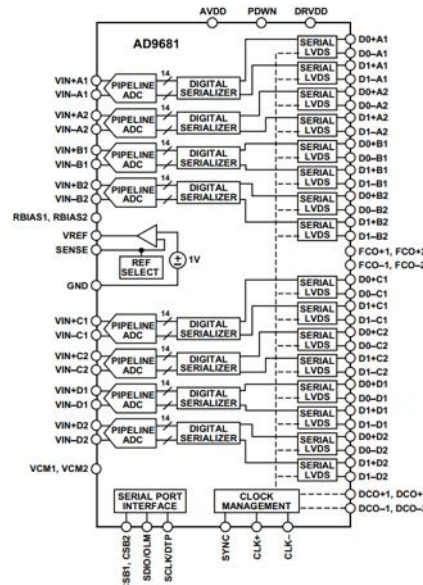
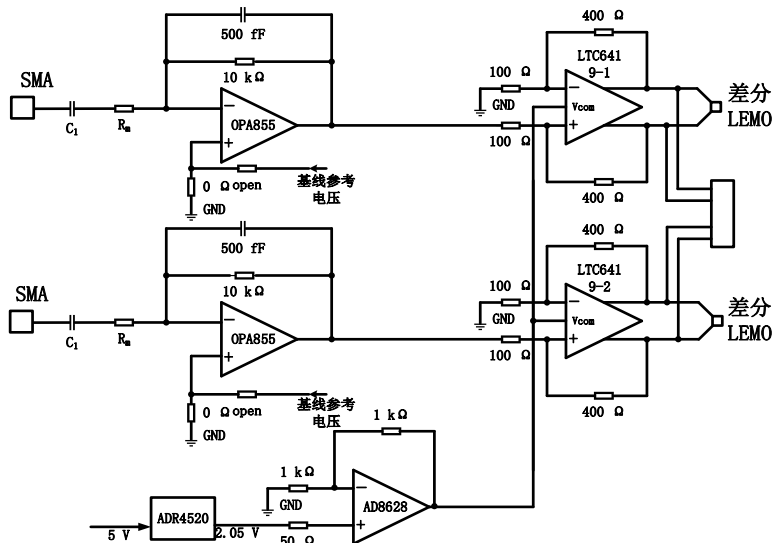


MDC Readout Electronics

- **Challenge: irregular pulse signals overlapping at high rates**
- **Attempt to separate overlapping pulses with waveform digitizing readout. A lot of effort on separation algorithm development and readout optimization.**
- **Developed readout circuit with discrete components (TIA + shaper + ADC). ASIC design also underway.**



Optimized ADC specs: 14 bit, sampling rate 125 MSPS, bandwidth 650 MHz

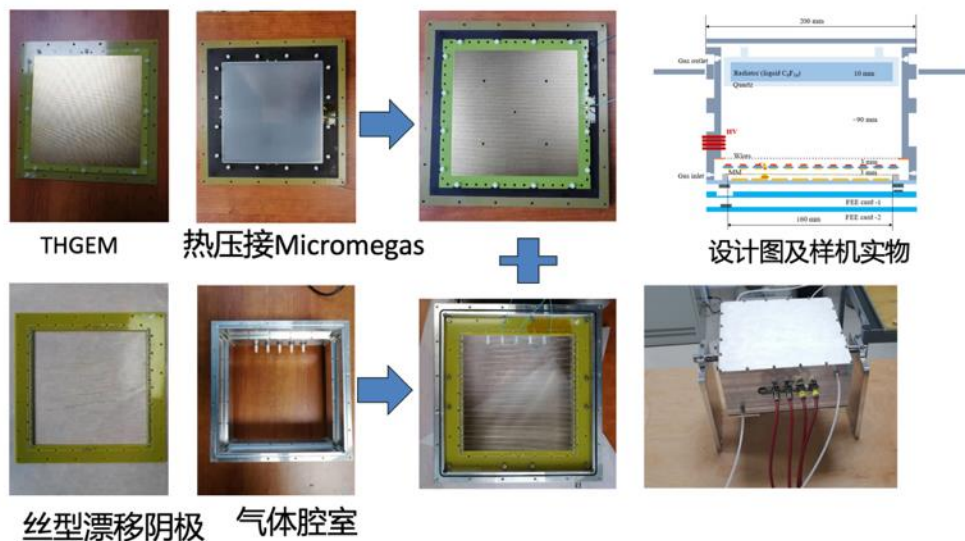


Readout board (16 chs) being tested



PID Barrel: RICH Detector R&D

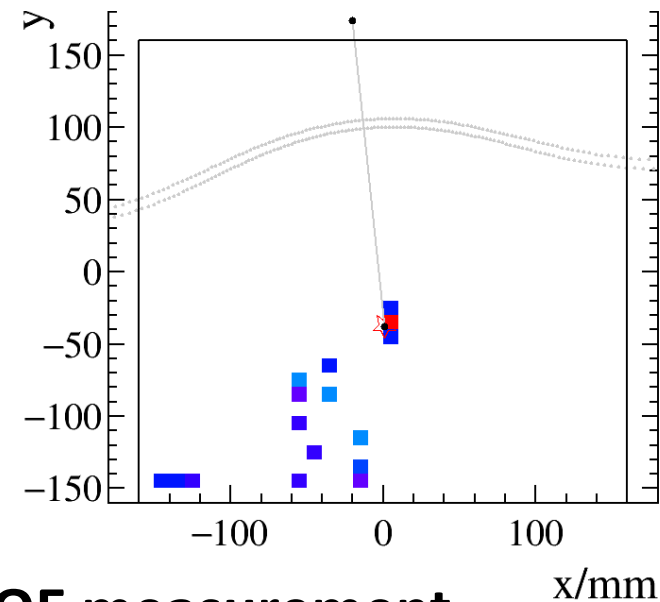
Fabrication of 30cm*30cm RICH prototype



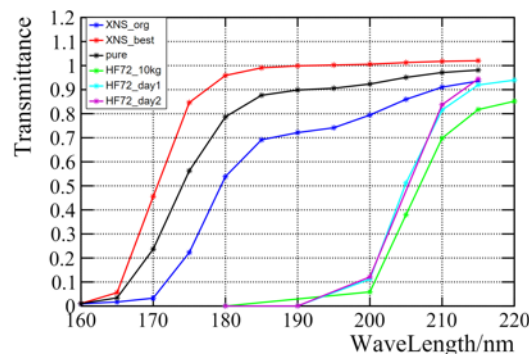
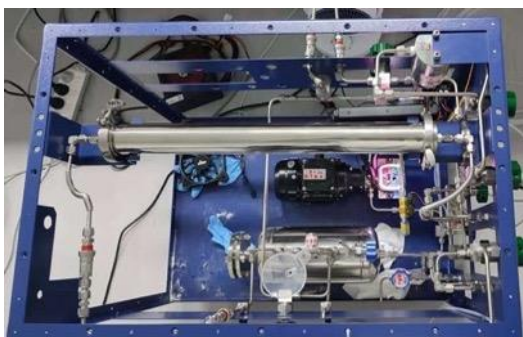
Cosmic-ray test



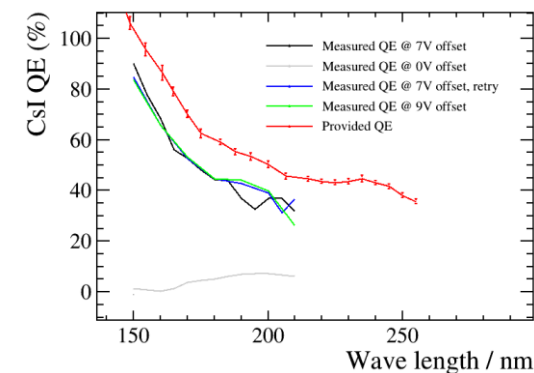
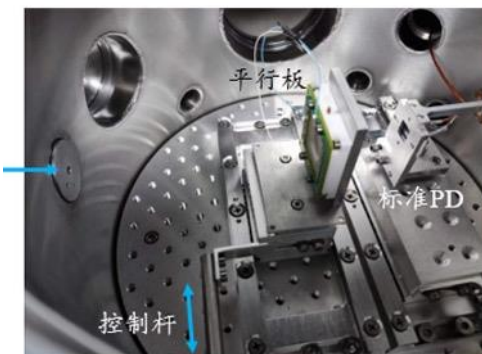
Very weak light observed Investigation ongoing



Radiator purifying

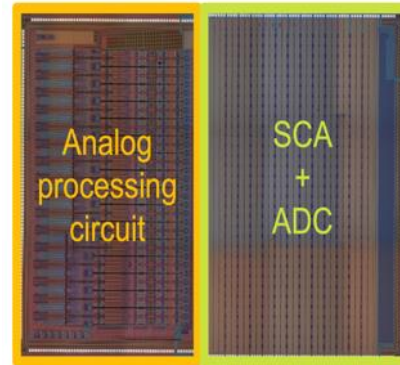
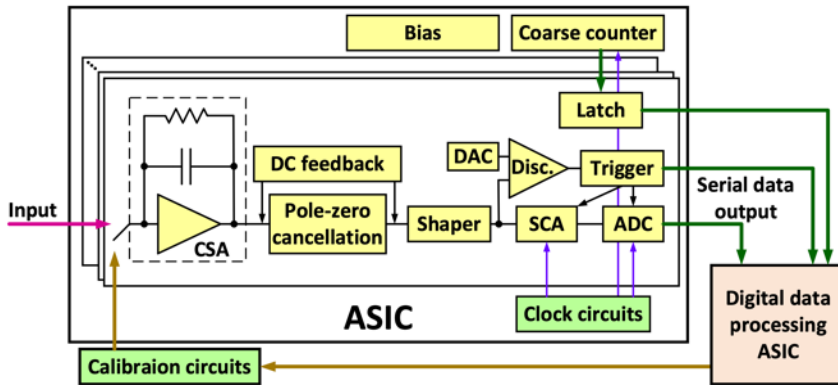


CsI coating and QE measurement

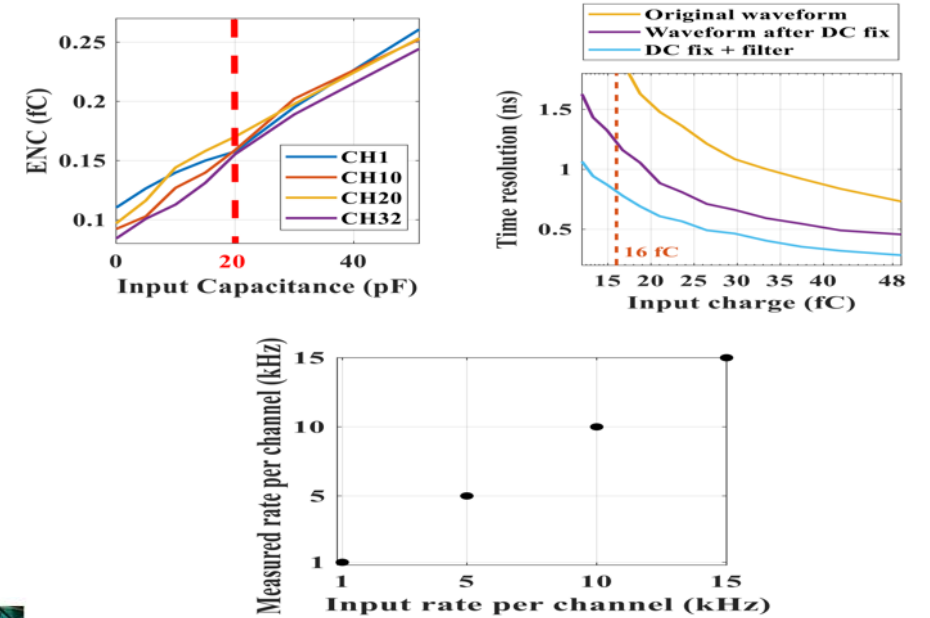


RICH Readout ASIC

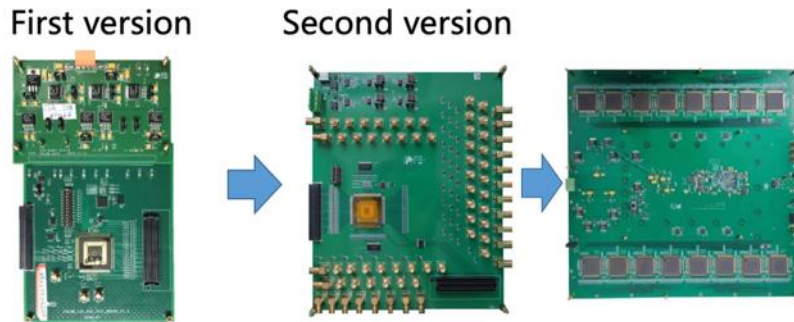
Design specs: $\sigma_t < 1\text{ns}$ @20fC&20pF,
event rate $\sim 100\text{ kHz}$, 32 channels



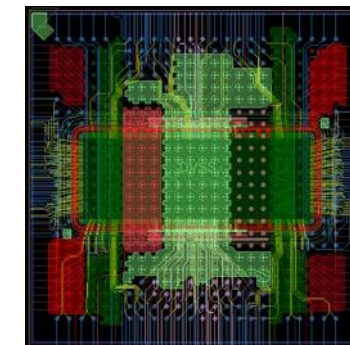
Test results



Design iterations

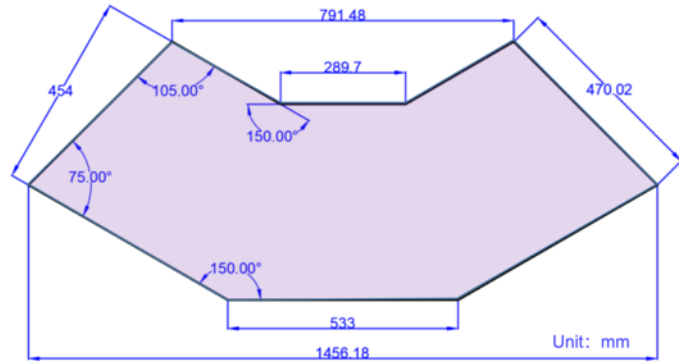


512-channel readout board
using the self-developed ASIC

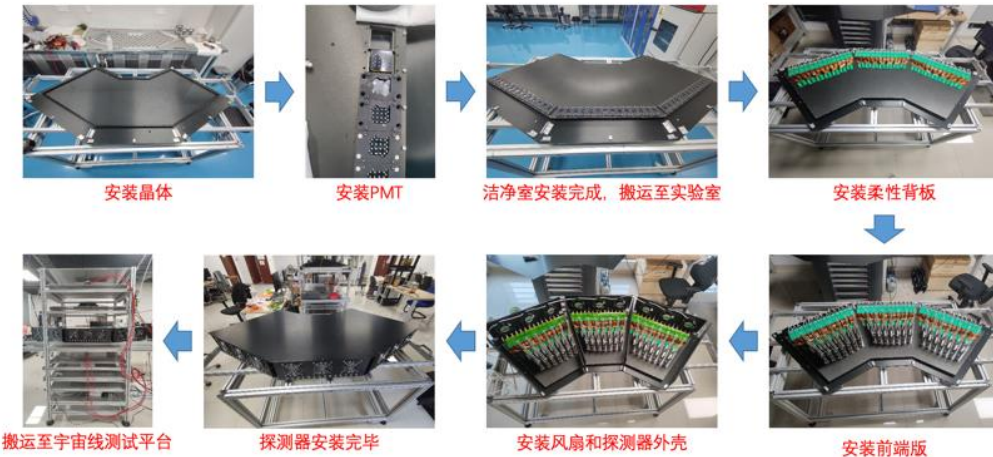


Design with
64 channels
is underway

PID Endcap: A full-sized DTOF prototype



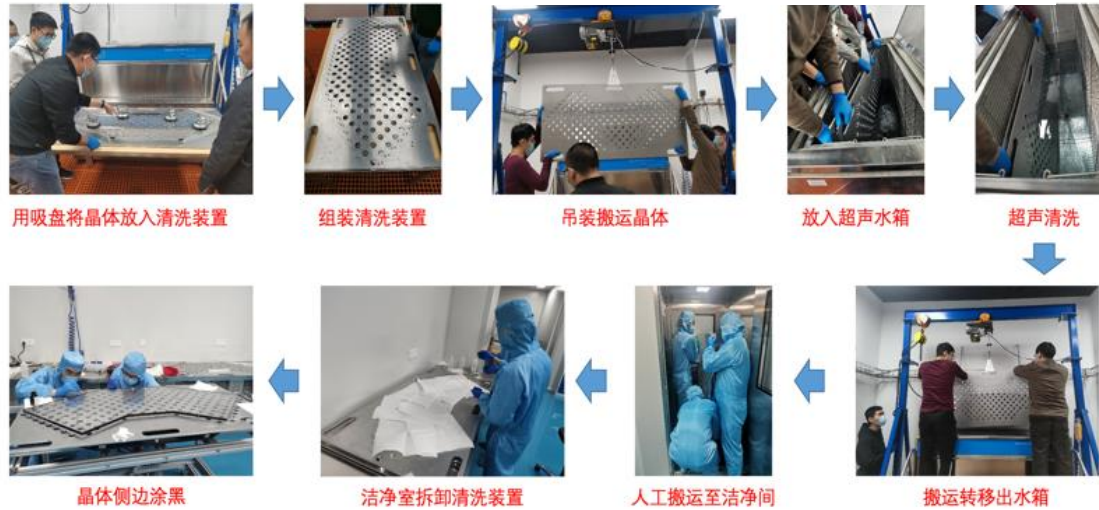
Detector assembling



Hamamatsu R10754

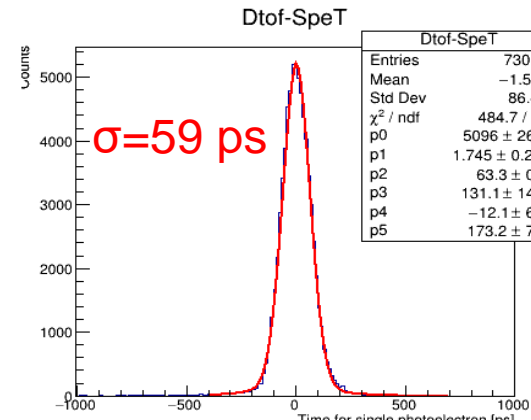
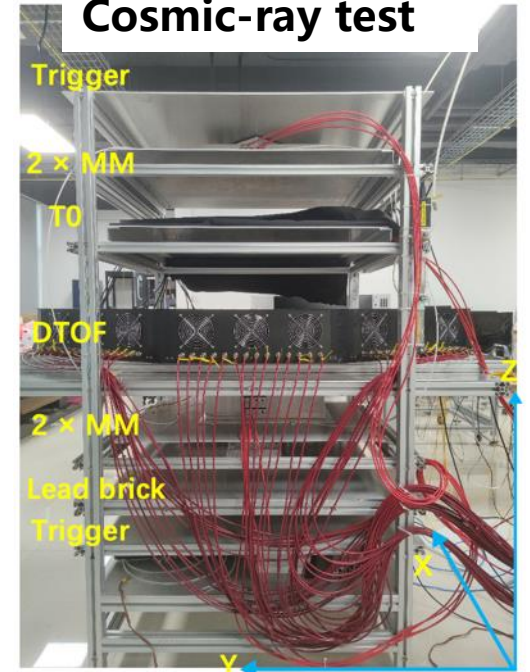
- 灵敏面积: 23×23 mm²
- 像素分布: 4×4 阵列
- 像素大小: 5.5×5.5 mm²
- 光谱响应范围: 200-850 nm
- 量子效率: 25% @λ=400 nm
- 单光子灵敏
- 高增益: >10⁶
- 增益非均匀性: 14% (σ/μ)

石英清洗和安装

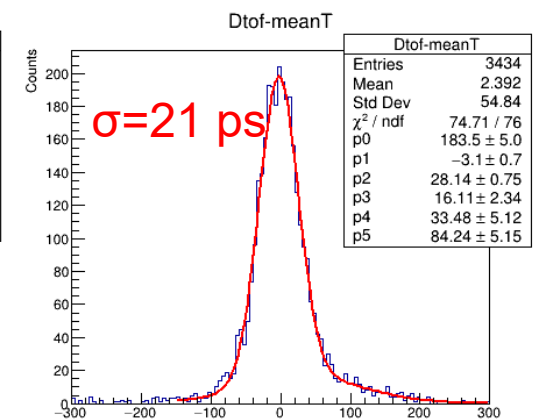


Quartz radiator cleaning and mounting

Cosmic-ray test



single photon time resolution



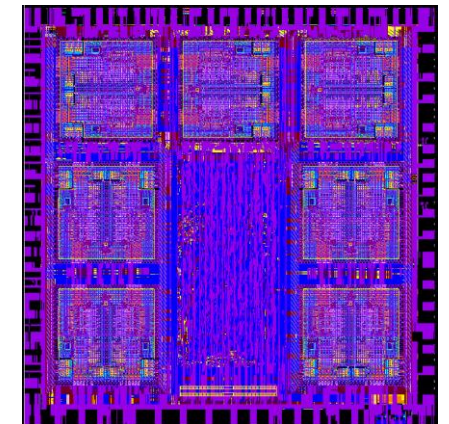
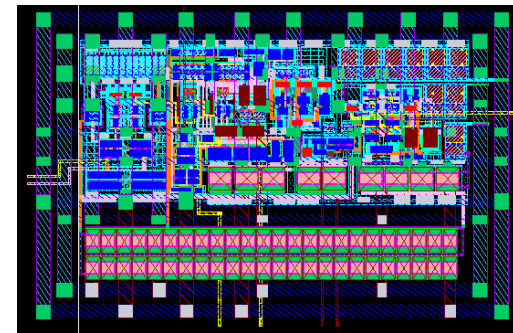
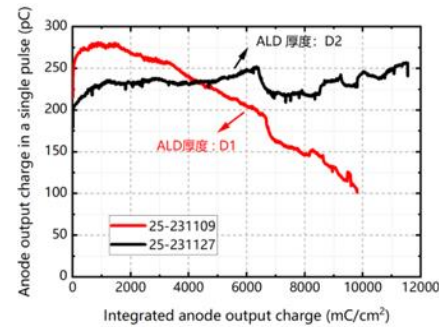
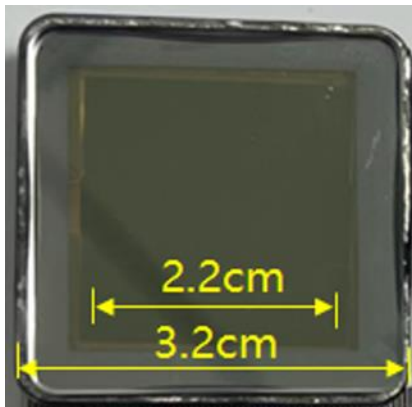
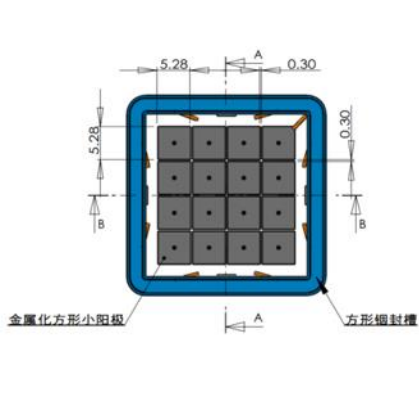
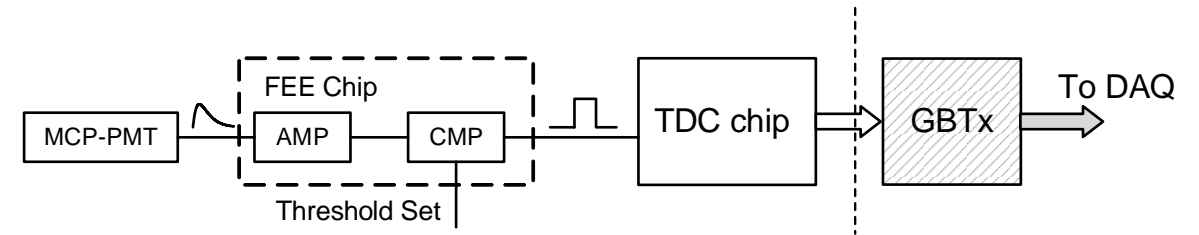
Single track time resolution

See <https://indico.cern.ch/event/1291157/contributions/5888464/> for details

DTOF R&D on MCP-maPMT and Readout ASICs

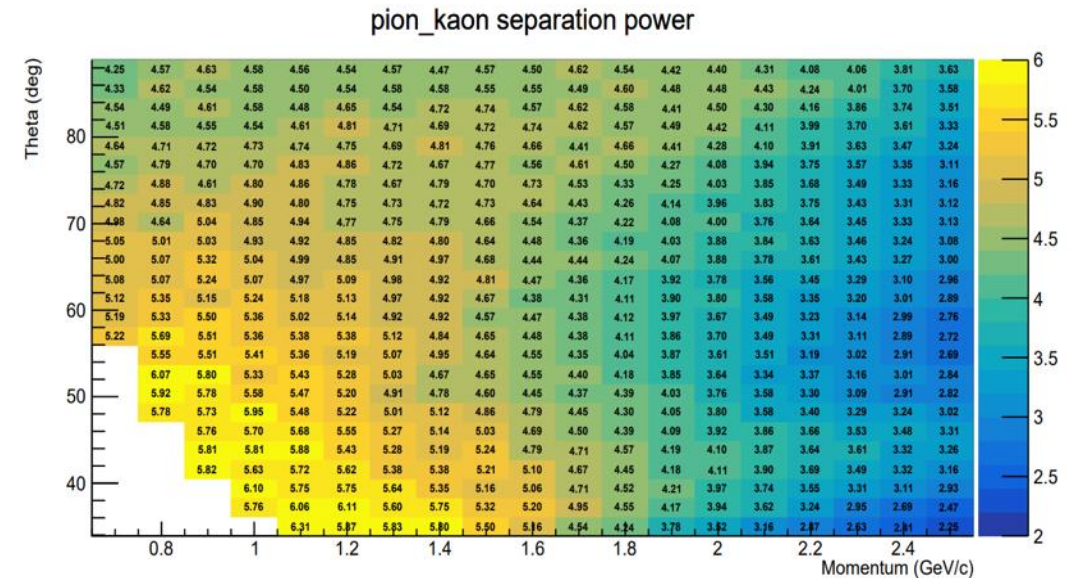
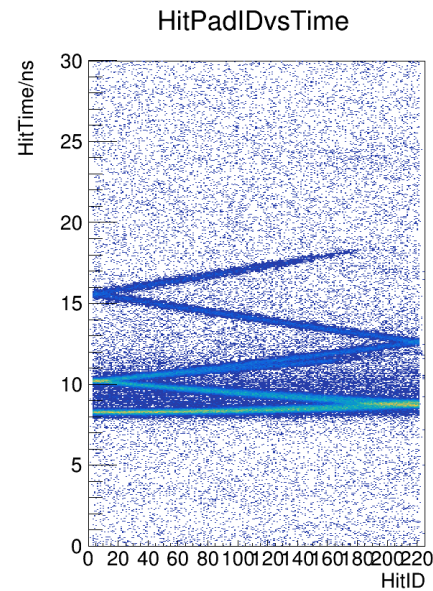
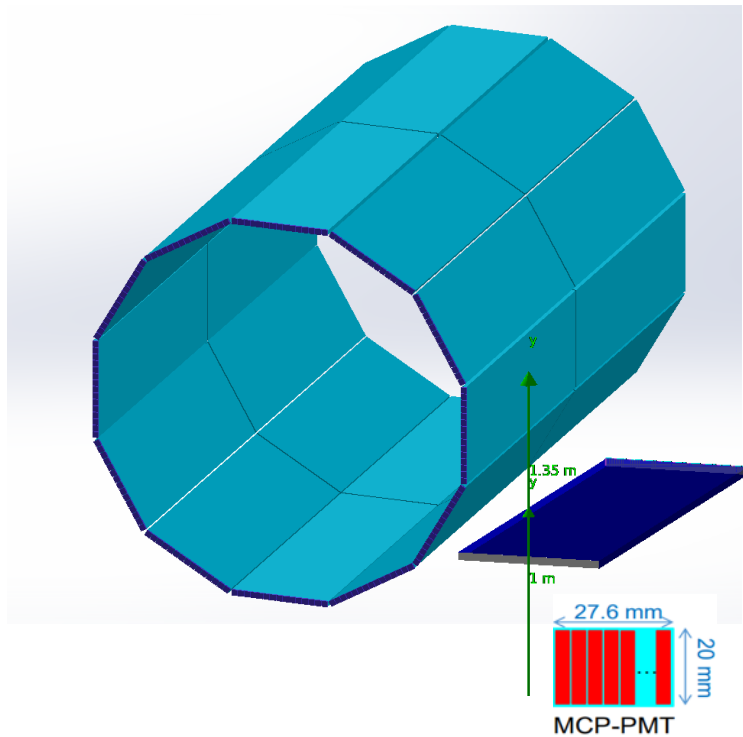
- MCP-maPMT: a critical component of the DTOF technology
- Designed and produced 1-inch MCP-maPMT with 16 annodes, TTS < 40 ps
- Intensive R&D on techniques (ALD and electron scrubbing) to produce long-life MCP-PMT (target > 10 C/cm²)

- Two ASICs designed for MCP-maPMT readout.
 - FET (to be taped out in July) ~ 15 ps
 - TDC (taped out) ~ 15 ps



Application of DTOF in Barrel

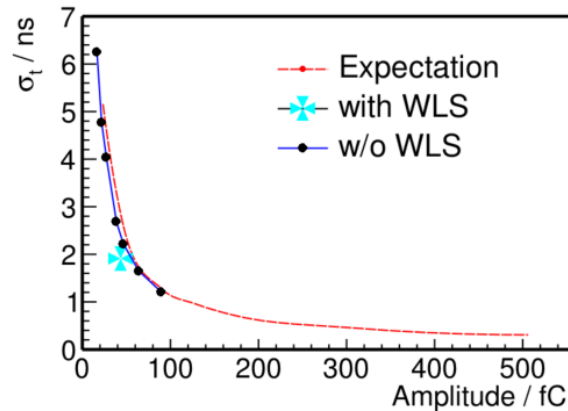
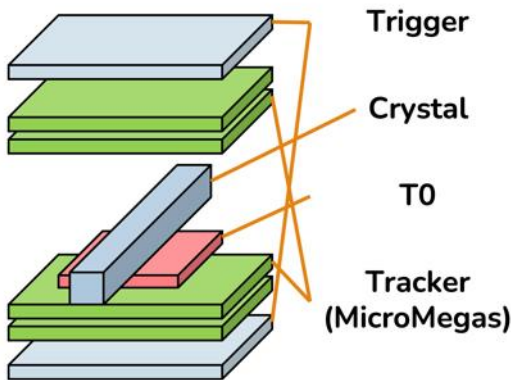
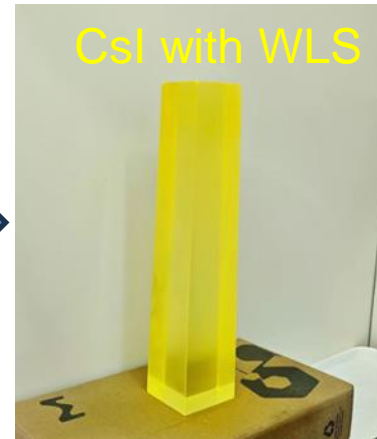
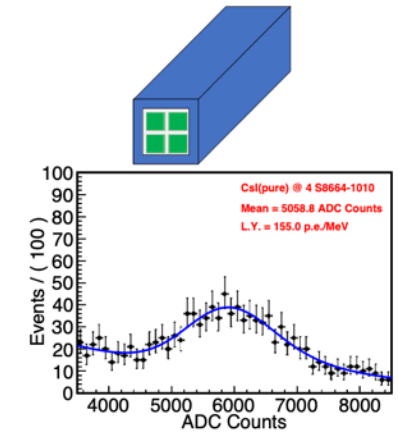
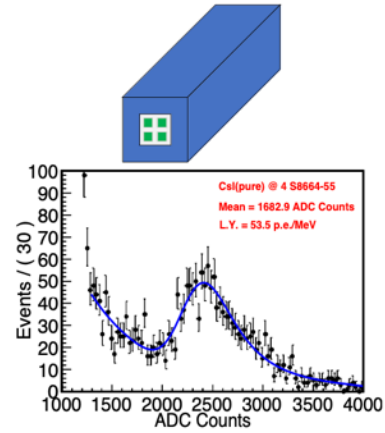
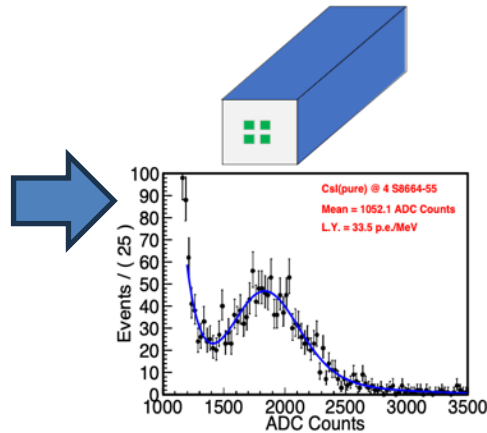
- Conceptual design of barrel PID based on the DTOF technology
- Design optimization by scanning a variety of key design parameters
- Performance with full simulation mostly meet PID requirements
- More studies and work are planned



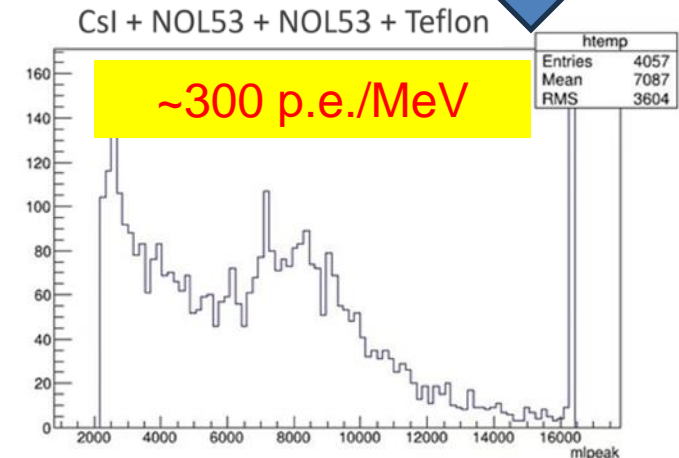
pCsI EMC : Light yield and timing studies

A major R&D task : enhancing light yield

reflector: 225um thick Teflon



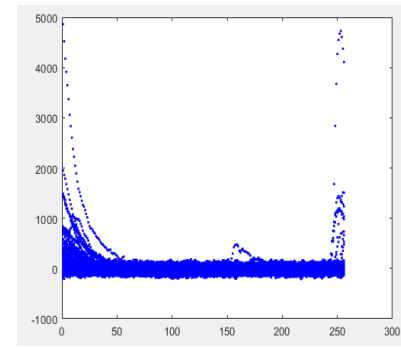
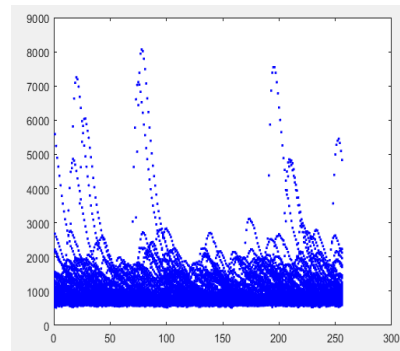
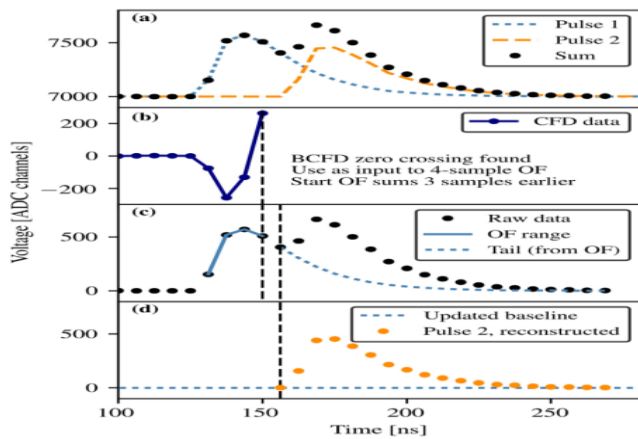
σ_t : 2.0 ns @ 0.03 GeV, 0.8 ns @ 0.1 GeV



Light yield reached up to 300 p.e./MeV

pCsl EMC : Pileup mitigation and electronics

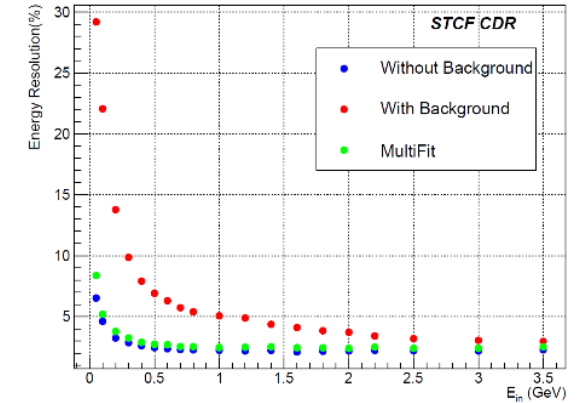
Waveform fitting to remove pileup noise (~1 MHz/ch) and extract signals



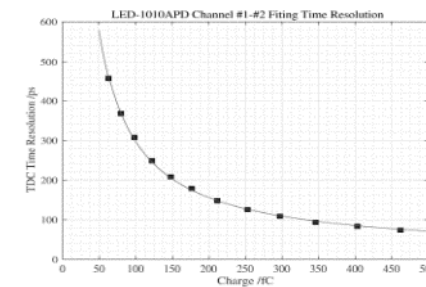
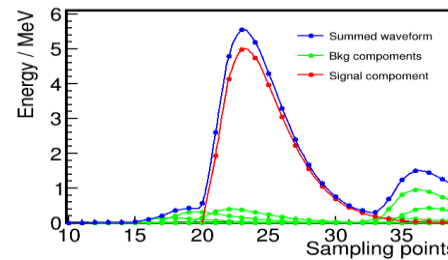
Before

After

Very effective in mitigating the pileup effect

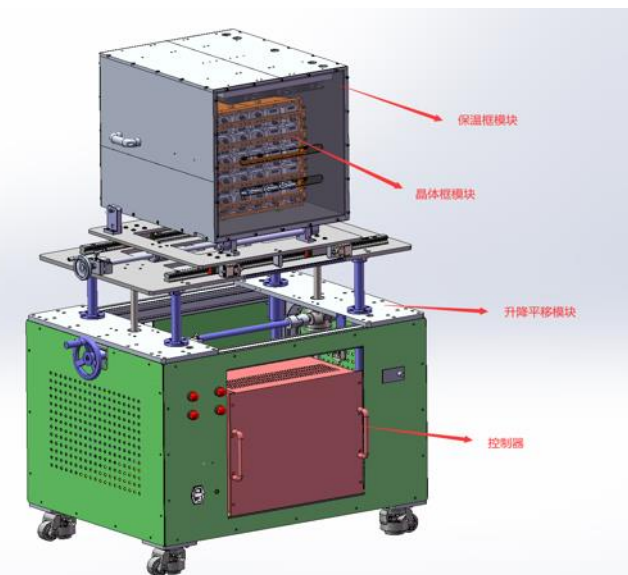
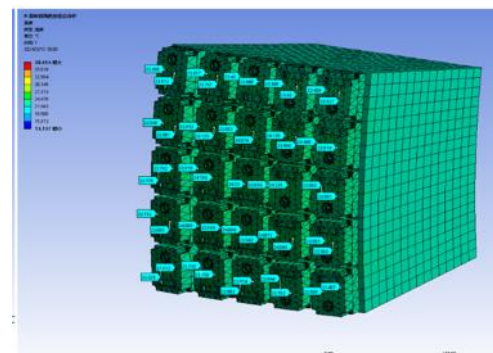
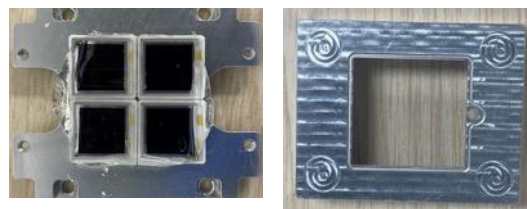
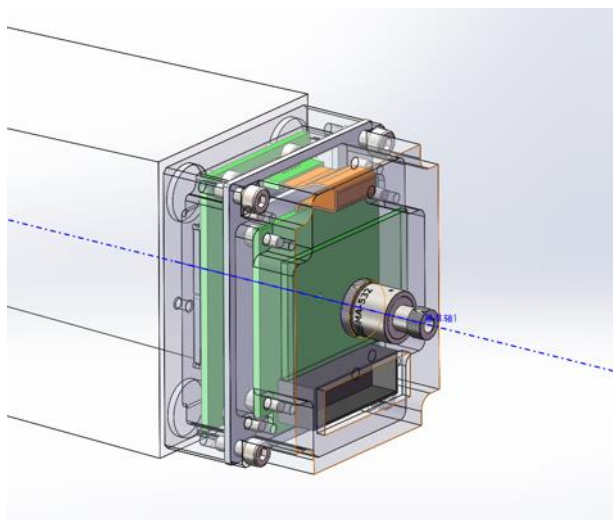


Development of waveform digitization electronics (CSA + shaper + ADC)



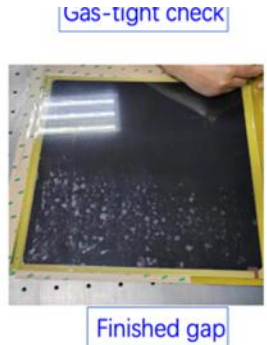
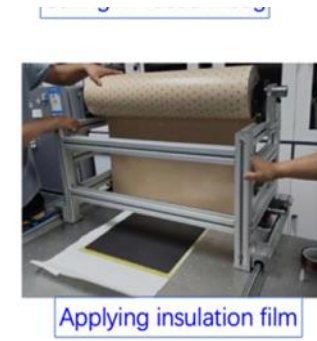
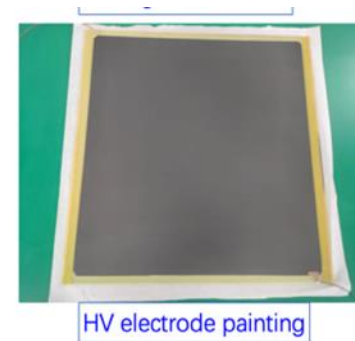
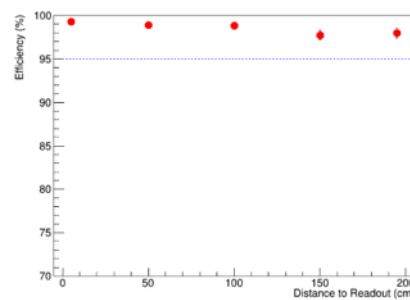
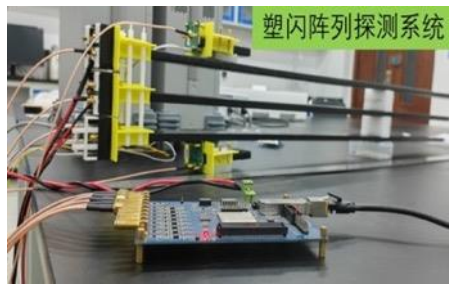
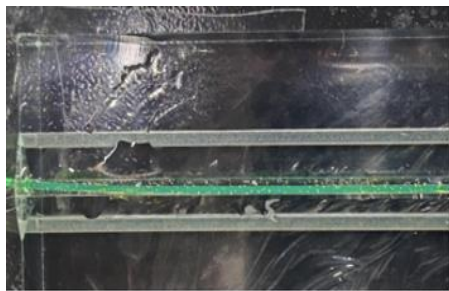
Dynamic range:
 3 MeV ~ 3 GeV
 ENE: ~ 0.4 MeV
 Time resolution :
 < 150 ps@1GeV

5 × 5 pCsl EMC Prototype

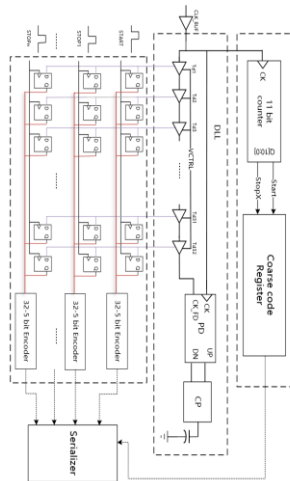
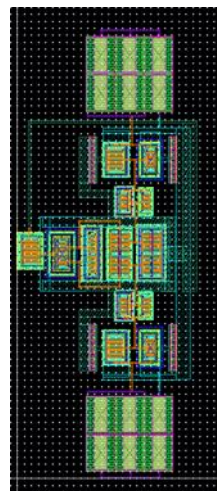
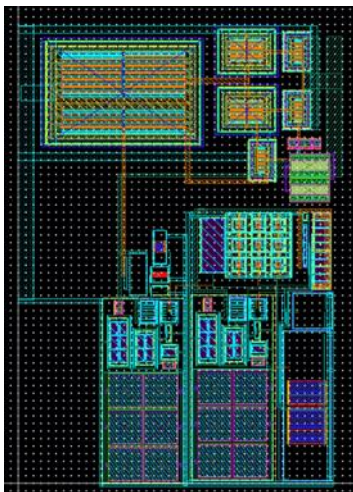


MUD R&D

- Fabrication and performance studies of large-sized scintillator strips and glass RPC

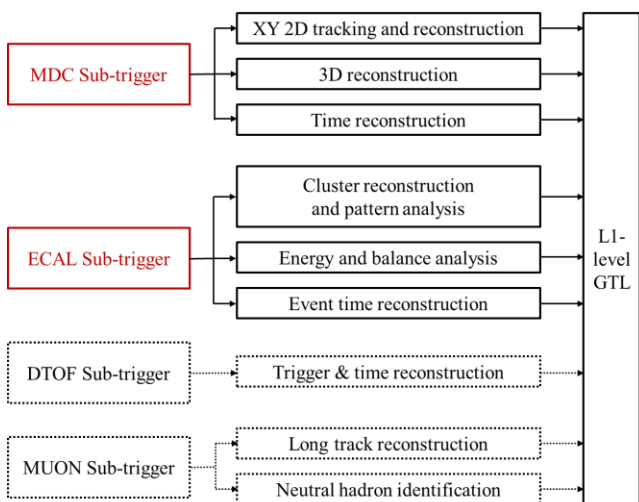
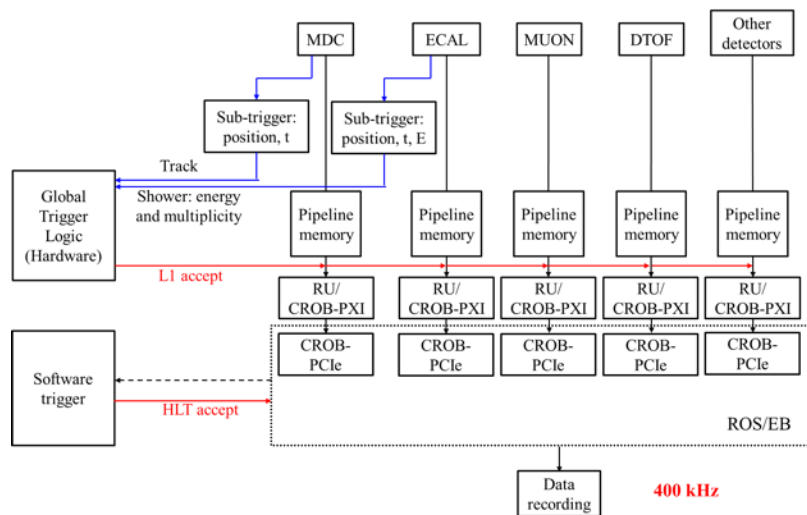


- Design of readout ASICs (FEE + TDC) is underway. Readout electronics with discrete components has been developed for detector testing and characterization



Trigger and DAQ

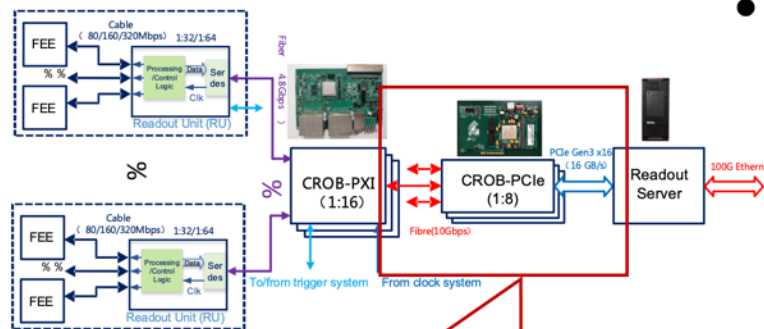
Physics event rate ~ 400 kHz



Component	Num. of channels	Readout time window	Event size (B)	Total (B/s)
ITK (Silicon)	50M	500 ns	14300	5.72G
ITK (μ RWELL)	10552	500 ns	17232	6.89G
MDC	11520	1 μ s	20400	8.16G
PID (RICH)	518400	500 ns	15600	6.24G
PID (DTOF)	6912	500 ns	7380	2.95G
EMC	8670	500 ns	15000	6.00G
MUD	41280	500 ns	262	105M
Total(Silicon)	50.6M	-	72.9k	29.2G
Total(μRWELL)	594k	-	75.9k	30.4G

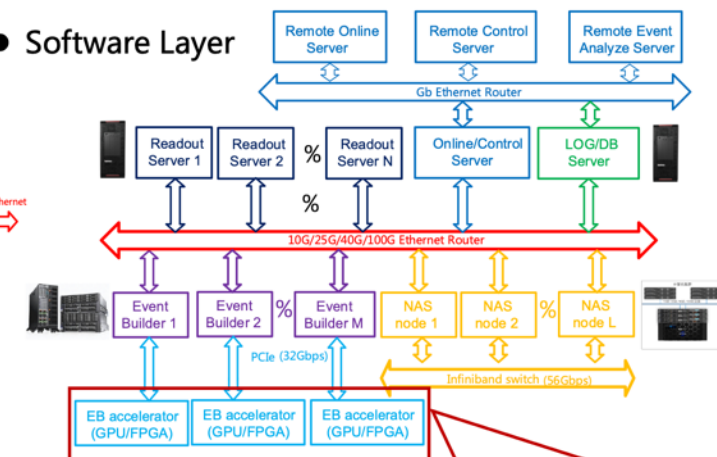
Raw data rate > 200 GB/s , triggered data rate ~ 30 GB/s

FPGA Layer



Optional:
FPGA 10G Ethernet core: FPGA \rightarrow Computer Farm

Software Layer

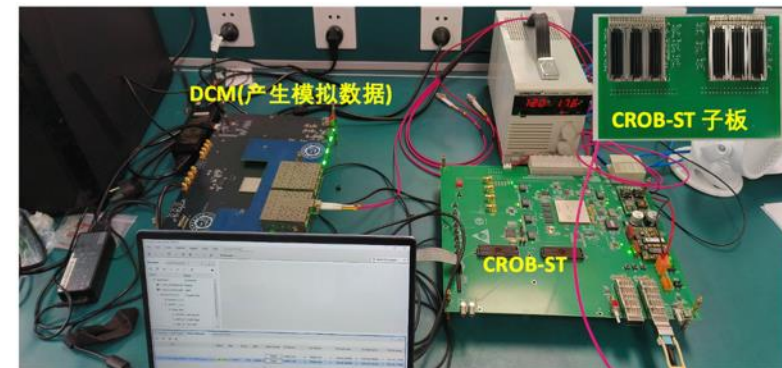
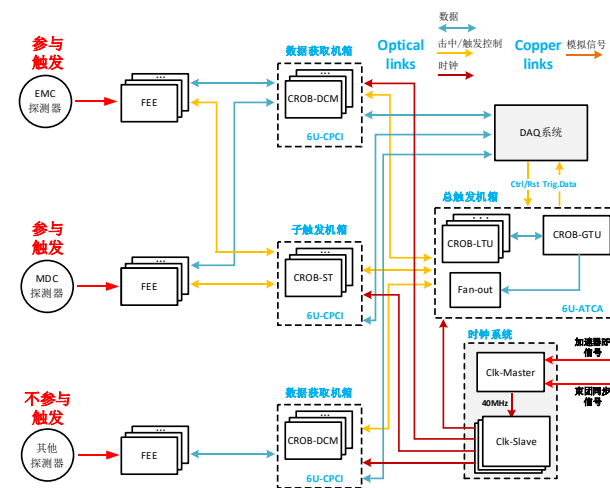
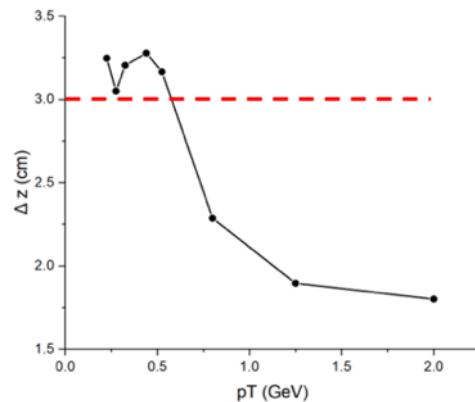
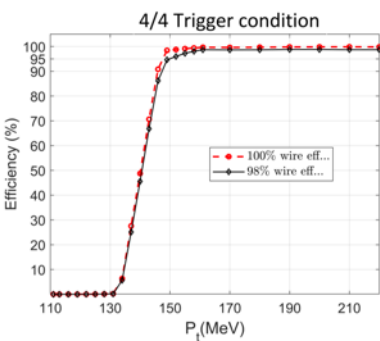
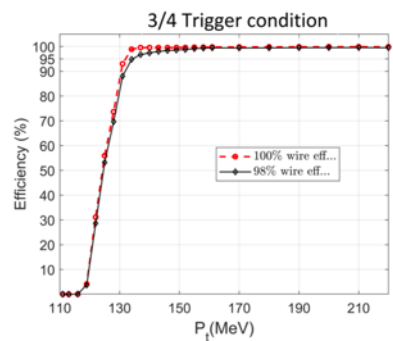
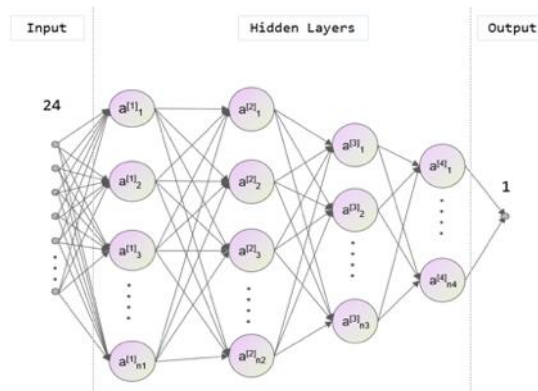
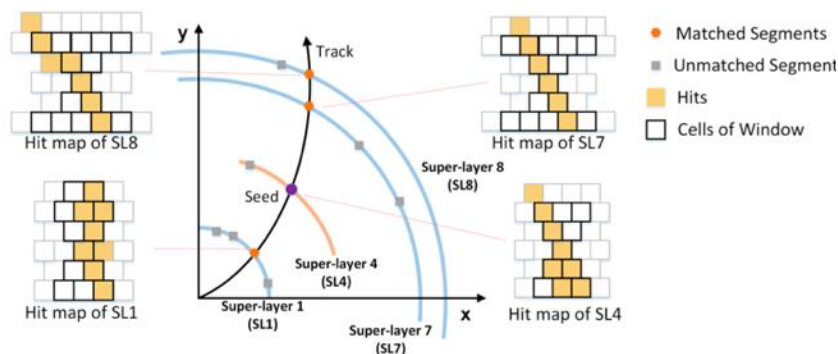


Optional: heterogeneous computing based on FPGA and/or GPU

Trigger Algorithms and hardware Development

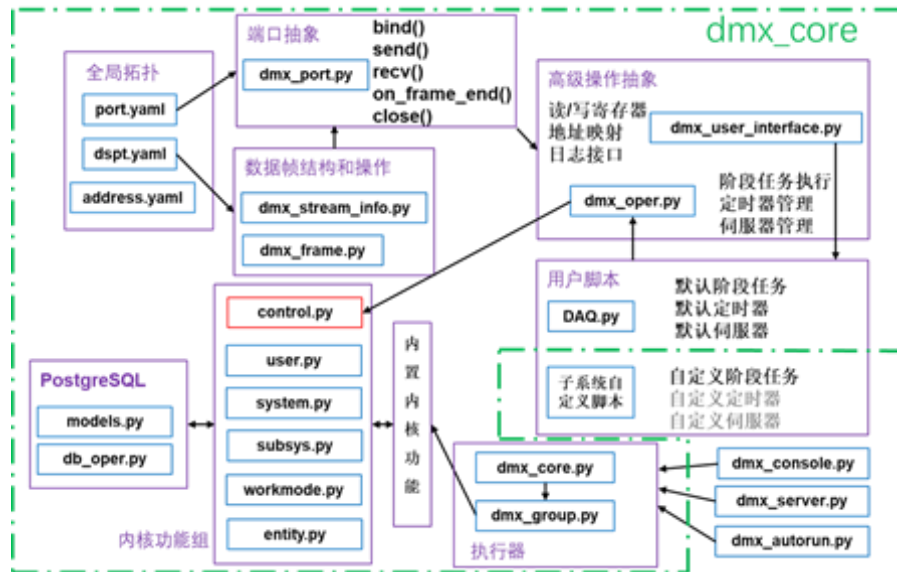
- MDC 2D and 3D tracking algorithms, EMC clustering algorithms, global trigger algorithms.
- PFQA programming to realize the algorithms

- Design of trigger electronics and development of core hardware components

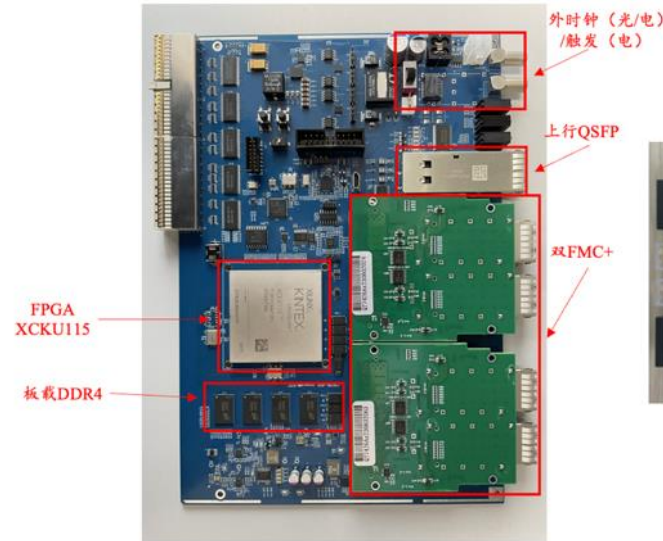


DAQ Software Design and Hardware Development

- Software and firmware architecture based on Data-Matrix: flow processing, hetero-computing, standard interfaces and protocols, global pipeline
- Development of core electronics boards: CROB-PXI, CROB-PCIe, FMCP optical interface board



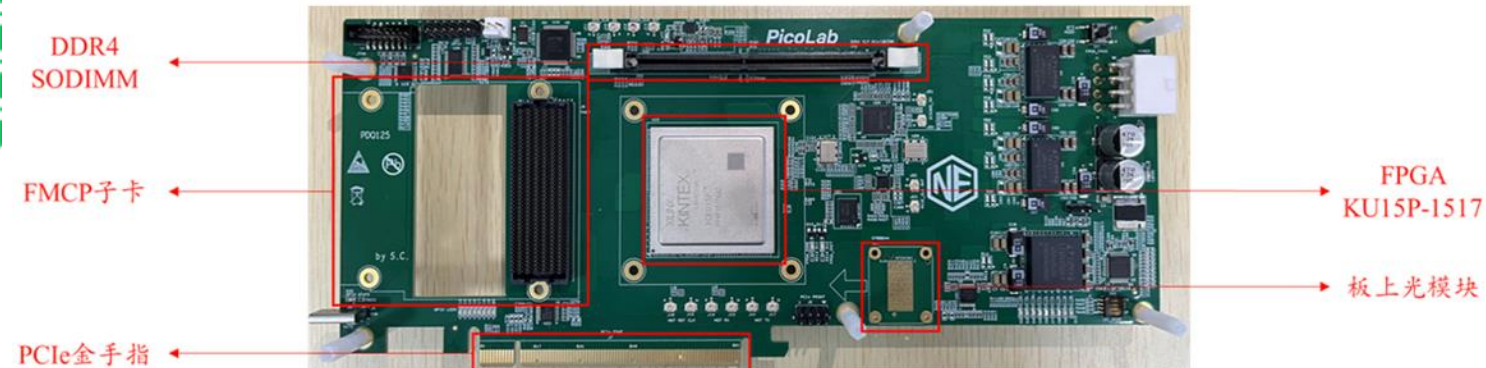
CROB-PXI board



FMCP optical interface board

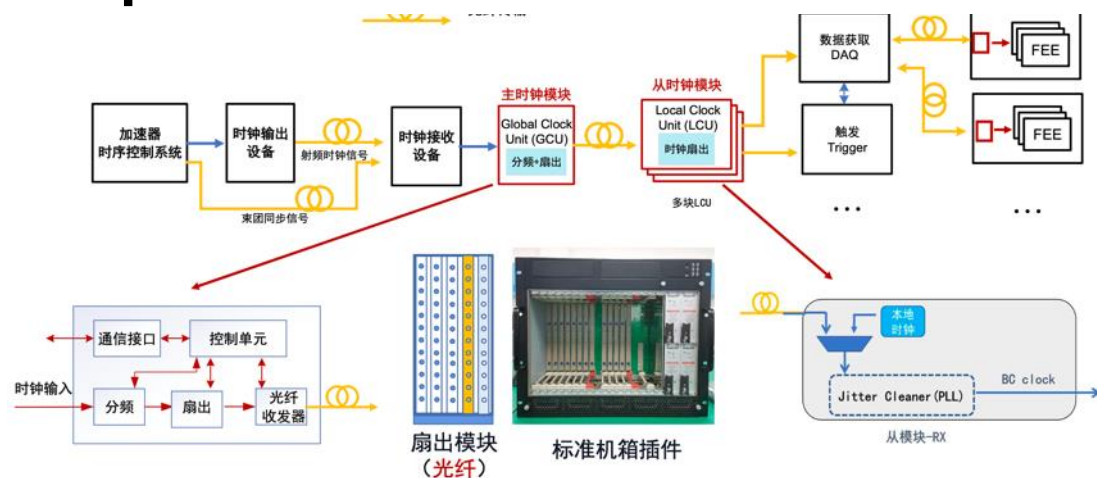


CROB-PCIe board



Clock and Data Transmission

- Master-slave clock distribution scheme : ~ 5ps

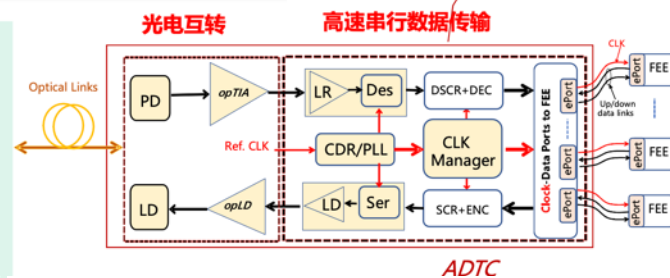


- High-speed data transmission : ~ 5Gpbs

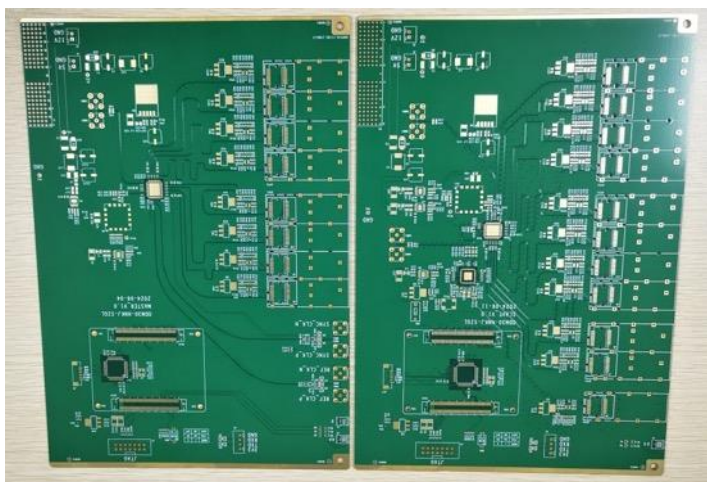


关键技术分为以下4个部分

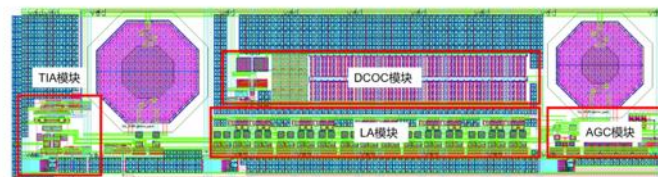
- 时钟模块
 - 时钟恢复 (CDR)、时钟锁相环 (PLL)、高精度时钟管理 (分频、移相、去噪等)
- 高速数据发送模块
 - 数据编码调制 (SCR+ENC)、串并转换 (SER)、光驱动及输出 (opLD+LD)
- 高速数据接收模块
 - 光接收 (PD+opTIA)、串并转换 (DES)、译码解调 (DSCR+DEC)
- 数据处理单元 (如控制译码、ePort接口等)



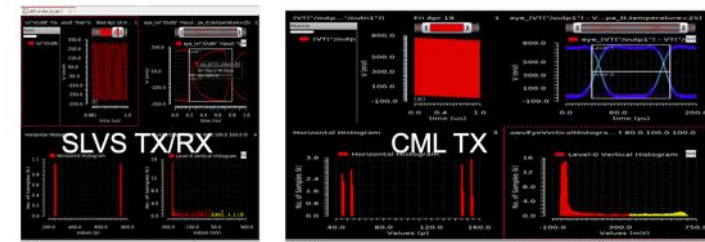
ADTC, an analogue of GBTx



激光器驱动芯片单通道模拟核心版图基本完成



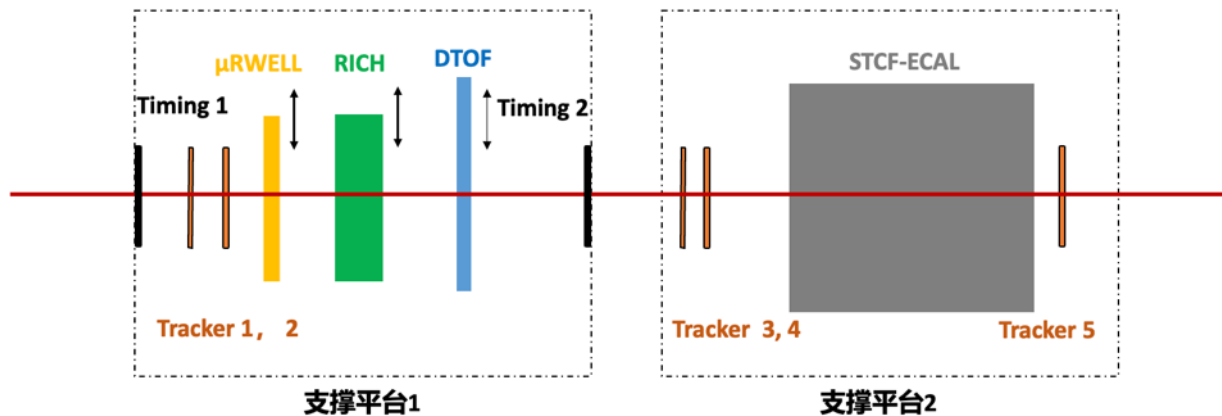
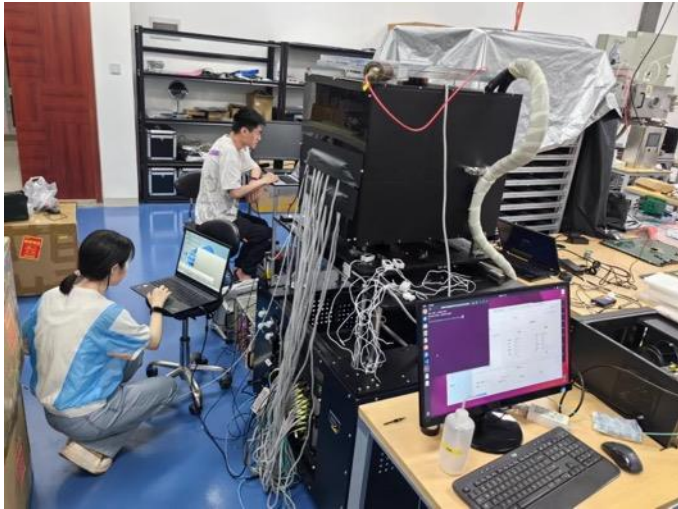
TIA跨导接收芯片单通道模拟核心基本完成



Clock management block

Test Beam Campaign

DTOF and EMC prototypes are combined in a single TDAQ system for test beams
The past two months were a frenzy of preparing and tuning the combined system, and packaging everything.



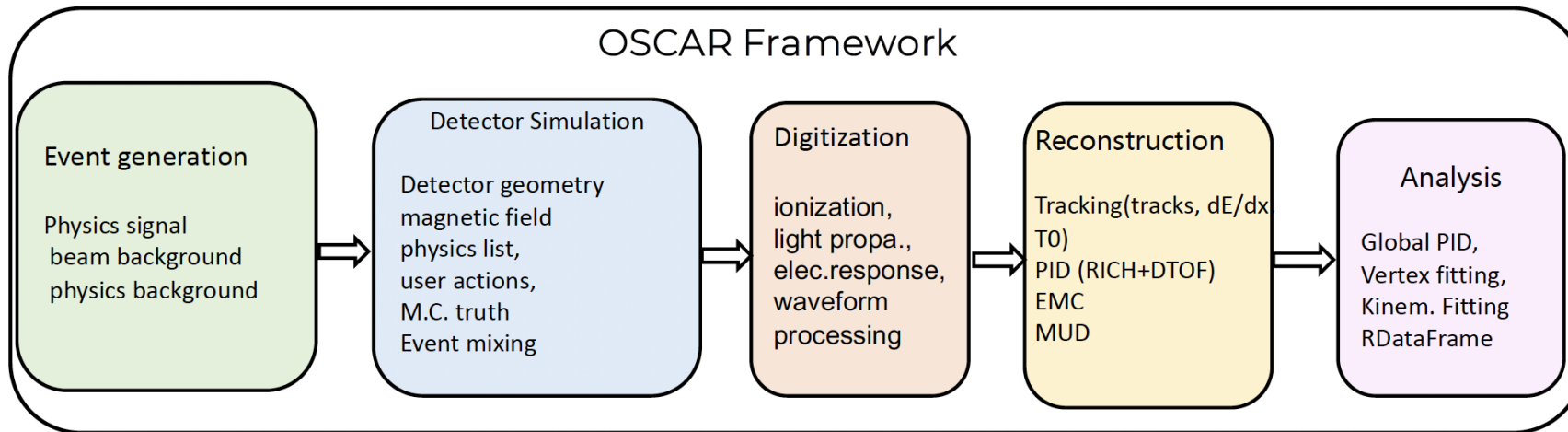
Starting from July 31
Lasting for 2 weeks
CERN PS T9 beam line

Offline Software of Super Tau-Charm Facility (OSCAR)

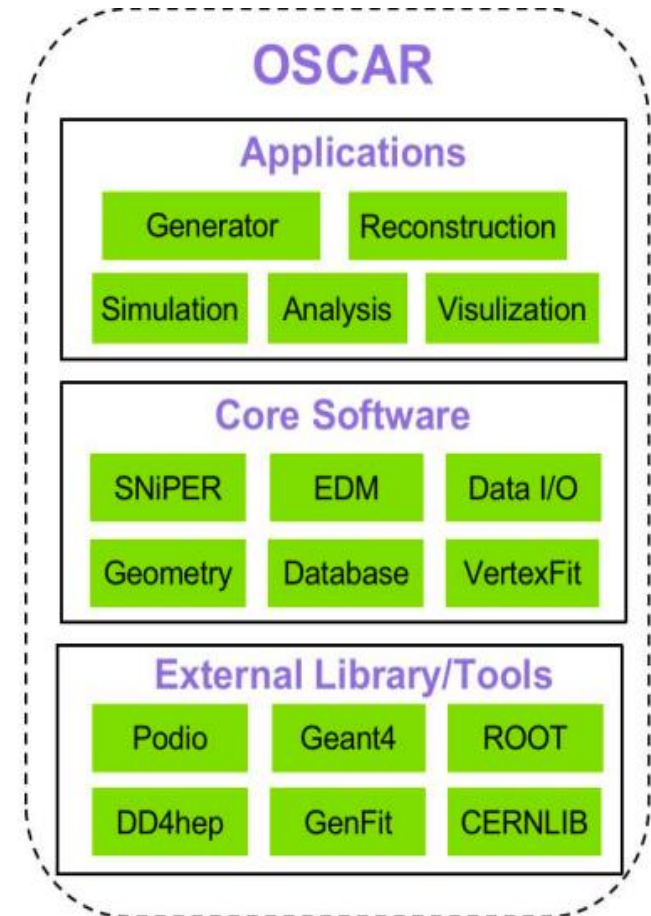
❖ OSCAR is based on light-weight and flexible **SNiPER** framework and adopted some state-of-the-art software and computing techniques

- **Podio** for Event Data Model
- **DD4hep** for detector description
- **TBB** for multi-threading
- **ONNX** for machine learning

❖ Established the **Full Chain** of the STCF offline data processing



Architecture of OSCAR: three layers



Summary

- **STCF detector conceptual design studies in the past few years have culminated with the publication of the physics and detector CDR.**
- **The STCF project has moved on to the technology R&D stage with strong support from local governments and USTC. A full STCF R&D program has been established and is rapidly moving forward.**
- **Intense R&D activities are underway on the baseline detector concept targeting key technologies of all sub-detectors. Significant progress has been made and some systems have reached milestones.**
- **It is crucial to expand collaboration and explore synergies with other projects.**

Thank you !